



Photoneo 3D Sensors

User Manual



Preface

Thank you for choosing the Photoneo™ 3D Sensor. Please, take a few minutes to read this manual and become familiar with the device.

For more information on our products, accessories, replacement parts, software, and services, see our website www.photoneo.com, or contact our team at [Help Center](#).

Purpose of the Manual

This manual provides information about the installation and setup of the Photoneo 3D Sensors and is designed for engineers, installers, and electricians who possess a general knowledge of automation.

Scope of the Manual

The manual provides information about the **Alpha 3D Scanner**, **PhoXi 3D Scanner**, and **MotionCam-3D (Color)** product lines. All models will be referenced as a “3D sensor”. For the full reference of Photoneo products, visit the website www.photoneo.com.

Notice: New Online Documentation

The latest, fully searchable version of this manual and all other 3D Sensor technical documentation is now available at docs.photoneo.com.

Table of Contents

Preface	2
Purpose of the Manual	2
Scope of the Manual	2
Table of Contents	3
Legal Information	6
Warning Notice System	6
Qualified Personnel	6
Proper Use of Photoneo Products	7
Trademarks	7
Products Overview	8
Product Identification	8
Laser Device	8
White LED optical radiation	10
Objects Suitable for Scanning	11
Scope of Delivery	12
Installation	12
Guidelines for Installation	12
Powering the Device & Data Connection	13
Powering Through PoE Connector	13
Powering by 24 V	14
External Grounding	14
Safety purposes	14
EMI reduction	14
Required tools:	15
Instructions:	15
Status LEDs	17
Supported Network Topologies	18
Mounting Restrictions	19
Using external casing for additional Ingress Protection	19
Movement During Scanning	20
Strong Electric Field	20
Clearance for Cooling and Wiring	21
Turning Off the Device	21
Laser Safety Interlock	21
Configuration	23
PhoXi Control	23
GenICam interface (Discontinued)	23
GigE Vision	24
Hardware Parameters	25
Powering the device	25
Power Over Ethernet Connector	25
Powering Requirements	25
24 V Power Connector (M12-A)	26
Powering Requirements	26

Hardware Trigger Characteristics	27
Trigger Input	27
Circuit Characteristics	27
Common Cathode	28
Common Anode	28
Input Signal Characteristics	28
Trigger Output	29
Circuit Characteristics	29
Output Signal Characteristics	29
Simplified wiring schemes	31
Projection Unit Properties	32
Environmental Conditions	33
Transport	33
Operation	33
Degree of Ingress Protection	33
Cleaning Instructions	34
Scanning Parameters	35
Datasheet Parameter Definitions	35
Standard Conditions	35
3D Sensing Technology	35
Output Data	35
Scanning Distance	36
Point-to-Point Distance	36
Scanning Time	38
Depth Map Resolution	38
Color Image Resolution	38
Frames Per Second	38
Dimensions	38
Baseline	38
Weight	38
Temperature Working Range	38
Projection Unit Laser Color	38
Power	39
Processing Unit	39
IP Rating	39
Data Connection	39
Tools for Infield Maintenance	40
Maintenance Tool	40
Marker Dots Correction	41
Autonomous Maintenance	41
Compliance with Standards	42
CE	42
Laser Classification	42
Dimensions and Illustrations	43
MotionCam-3D Color (Blue)	43
Bottom View: Mounting Plate	43
Bottom View: Detail A	44

Front View: Projection Unit and Camera Unit	45
MotionCam-3D Color (Red)	46
Bottom View: Mounting Plate	46
Bottom View: Detail A	47
Front View: Projection Unit and Camera Unit	48
MotionCam-3D Version A	49
Bottom View: Mounting Plate	49
Bottom View: Detail A	50
Front View: Projection Unit and Camera Unit	51
MotionCam-3D Version B	52
Bottom View: Mounting Plate	52
Bottom View: Detail A	53
Front View: Projection Unit and Camera Unit	54
PhoXi 3D Scanner Gen 3	55
Bottom View: Mounting Plate	55
Bottom View: Detail A	56
Front View: Projection Unit and Camera Unit	57
PhoXi 3D Scanner Gen 2	58
Bottom View: Mounting Plate	58
Bottom View: Detail A	59
Front View: Projection Unit and Camera Unit	60
Alpha 3D Scanner	61
Bottom View: Mounting Plate	61
Bottom View: Detail A	62
Front View: Projection Unit and Camera Unit	63
Warranty	64
Contact Information	64

Legal Information

Warning Notice System

This user manual contains notices that should be observed to ensure personal safety, as well as prevent damage to equipment. The notices referring to personal safety are highlighted with a safety alert symbol, while notices referring only to equipment do not have a safety alert symbol. The notices are graded according to the degree of danger.

WARNING

Indicates that death or severe personal injury may result if proper precautions are not taken.

CAUTION

When a safety alert symbol is shown, it indicates that a minor personal injury can result if proper precautions are not taken.

CAUTION

When no safety alert symbol is shown, it indicates that equipment damage can result if proper precautions are not taken.

NOTICE

Indicates that an unintended result or situation can occur if the relevant information is not taken into account.

If more than one degree of danger is present, the warning notice representing the highest degree of danger is used. A notice warning of injury to persons with a safety alert symbol may also include a warning relating to equipment damage.

Qualified Personnel

The device described in this documentation may be operated only by **qualified personnel**. Qualified personnel means those who, based on their training and experience, are capable of identifying risks and avoiding potential hazards when working with this device.

Installation, commissioning, use, decommissioning, and disposal of this device should be done following relevant documentation, in particular, its warning notices, and safety instructions.

Photoneo 3D Sensors are either Laser Class 3R or Laser Class 2 devices. More information is available in the [Projection Unit Properties](#) and [Compliance with Standards](#) sections.

Proper Use of Photoneo Products

Please note the following:

WARNING

Photoneo products may only be used following relevant technical documentation. If products and components from other manufacturers are used, these must be recommended or approved by Photoneo. Proper transport, storage, installation, assembly, commissioning, operation, and maintenance are required to ensure that the products operate safely and without any problems. The permissible ambient conditions for storage or operation of the device must be complied with. All information provided in the relevant documentation must be observed.

Trademarks

Copyright© 2025 by Zebra Technologies Slovakia s.r.o., Bratislava, Slovakia

Photoneo™, PhoXi™ Control, PhoXi™ 3D Scanner, MotionCam-3D are registered trademarks of Zebra Technologies Slovakia s.r.o.

Products Overview

Photoneo provides two main families of 3D area scanning devices:

MotionCam-3D (Color) is a high-accuracy and high-resolution snapshot 3D area scanning device for large work areas that can be in arbitrary motion. The product is based on a patented CMOS sensor and Parallel Structured Light technology developed by Photoneo. It provides the scanning quality of sequential structured light devices with the ability to scan dynamic scenes.

PhoXi 3D Scanner and **Alpha 3D Scanner** use a sequential structured light projection to reconstruct the 3D surface geometry of a static scene or object at very high resolution and quality.

All Photoneo 3D Sensors provide onboard calculations of the data which are provided to the user in multiple data formats: depth map, point cloud, normals, and confidence. Data is transferred to the computer running the driver software (see [PhoXi Control](#) manual) via a 1Gbps Ethernet connection.

Product Identification

The device description and the manufacturer can be located on the back panel of the device.



Label with manufacturer address, product name, and model, CE, FCC, WEEE, and RoHS marks, country of origin, and input options. Scanning the QR redirects the user to the website of the specific model.

Laser Device

⚠ WARNING

This device is a laser product. Do not deliberately look into the laser beam. This may cause injury to the retina. The use of protective eyewear is normally not necessary. The laser class label is present on the back of the device.

The laser projector aperture is located on the right side of the front panel of the device (Figure 1). The aperture is marked with a warning label. Do not look directly into the laser projector while the device is in use. Laser Class and Laser parameters used in our devices are discussed in the chapter [Projection Unit Properties](#).

To avoid unauthorized contact with the scanner or unintentional viewing of the laser beam, it is recommended to locate the device in a restricted area and take measures to restrict laser light exposure to the surroundings. Although diffuse reflections are not harmful, users should remove mirrors, polished objects, and similar items from the vicinity of the scanner to avoid specular reflections.

All components of the device, including those sourced from 3rd party suppliers, conform fully with all applicable European directives and regulations.



Figure 1: Photoneo scanning device laser aperture location



Laser radiation hazard warning symbol.



Laser aperture label. Designates the place from which laser radiation is emitted.

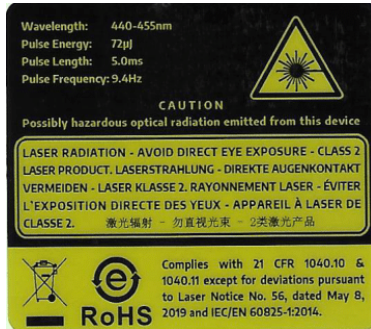
The device uses the following labels and warning systems. Apart from the laser aperture label, all are located on the back panel of the device.

Laser Class 3R devices



Laser radiation warning with laser class label. The serial number of the device can be found above the warning labels. Label specifying parameters such as wavelength, pulse energy, and pulse length of the laser. (left - blue; right - red)

Laser Class 2 devices



Laser radiation warning with laser class label. The serial number of the device can be found above the warning labels. Label specifying parameters such as wavelength, pulse energy, and pulse length of the laser. (left - blue; right - red)

White LED optical radiation

⚠ WARNING

Do not stare at the operating lamp. May be harmful to the eyes.



Figure 1: Photoneo scanning device laser aperture location



Visible radiation symbol. IEC 60417-6041:2010-08 for retinal blue light hazard and Retinal thermal hazard.

Objects Suitable for Scanning

Photoneo 3D sensors are measurement devices working on the principle of optical triangulation. Modulated light projected from the projection unit is reflected by the scanned object and captured by a camera unit based on which the distance to the object is computed.

For **PhoXi 3D Scanners** and **Alpha 3D Scanners**, which operate on the principle of sequential structured light, the scene must be completely static during the scan.

For **MotionCam-3D (Color)**, which uses the revolutionary and patented principle of Parallel Structured Light™, the scene can be in arbitrary movement or vibration.

As both systems rely on the reflection of projected light, objects most suitable for scanning are (including and not limited to):

- rough surface objects, for example, wood, rubber, paper, plaster, etc..
- objects with a matte finish, such as sand-blasted aluminum, cast iron, etc..
- molded, unpolished plastic materials,
- fruits, foods, skin, textiles, plants.

Some objects not suitable for scanning (including and not limited to):

- mirrors and polished metals,
- most liquids (e.g., water, oil),
- translucent and transparent objects (e.g., glass, transparent plastic).

Smoke and particles dispensed in the air still negatively influence the 3D data.

Scope of Delivery

- Selected model of Photoneo 3D Sensor
- Desktop PoE injector (input: 90 ~ 264 VAC, output: 33.6 W, 56 V, IEEE802.3at) with power cable (1.8 m)
- Ethernet cable M12-X male - RJ45 male, 5 m, PUR
- Quick Start Guide and Datasheet

NOTICE

Software components are needed for the operation of the scanner. See the section [Configuration](#) for more information.

Installation

Guidelines for Installation

A Photoneo 3D Sensor is designed to allow easy installation.

The device can be mounted¹:

- Using a mounting plate of suitable size and 4 M4 screws.
 - This is the preferred mounting method to ensure rigid mounting of the device to avoid unwanted movement
- Using an M8 screw.
- On a tripod using a 3/8-16 UNC screw.

To install the device:

1. Mount the device using any preferred method. Refer to [Dimensions and Illustrations](#).
2. When mounting the scanner, ensure that an appropriate scanning distance is set between the scanner and the scanned object and eliminate any potential obstacles.

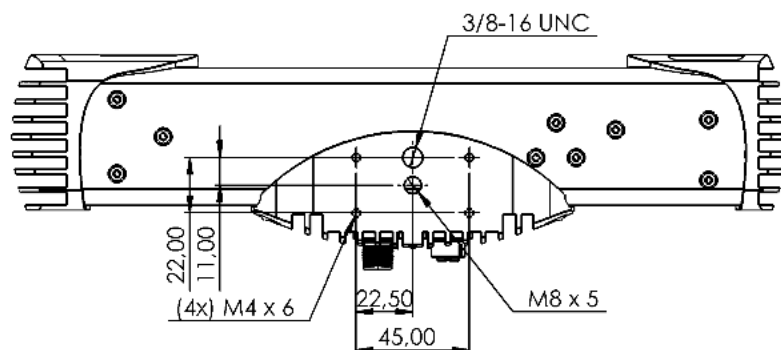


Figure 2: Mounting plate

¹ A CAD models of the Photoneo 3D Sensors are available at: [Device Resources - Photoneo](#)

3. Connect the device to the computer or local network and plug it into the power. See the section [Powering the device & Data connection](#) for more details.
4. Download and install the PhoXi Control application from the Photoneo webpage.
5. Run the PhoXi Control application and try to make your first scan. Please refer to the PhoXi Control user Manual at <https://photoneo.com/kb/pxc>.

⚠ WARNING

Hot surface warning

The surface of the processing unit becomes hot to the touch when the device is in use. Mount the device on a metal mounting plate that will act as a thermal bridge to dissipate the heat, or use the carbon body to manipulate the device.

Powering the Device & Data Connection

There are two possibilities for how to power the device:

1. Using the M12-X Power over Ethernet (PoE) connector (providing both power and data connection)
2. Using the M12-A 24 V power connector to power the device and the M-12X connector for data transfer

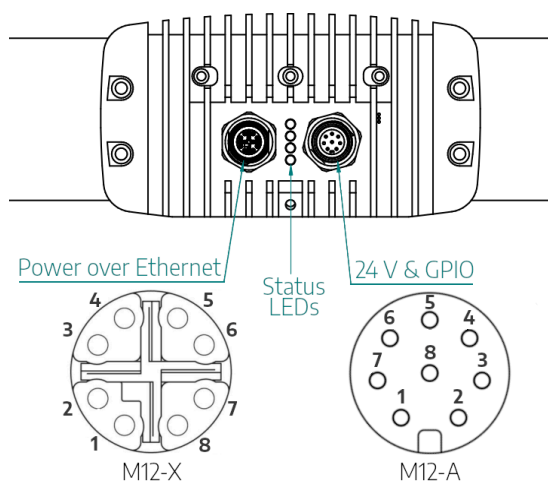


Figure 3: Back panel of the Photoneo scanning device

Powering Through PoE Connector

1. Connect 1 Gbps capable (not included in the packaging) Ethernet cable to the PoE injector "DATA" port
2. Connect the M12-X RJ45 cable to the sensor and to the PoE injector "DATA + POWER" port
3. Plug in the power cable of the PoE injector

NOTICE

It is recommended to use a PoE connection to power the device.

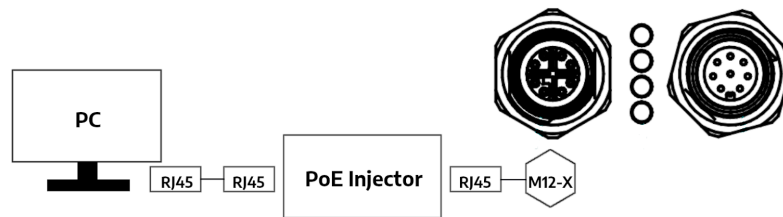


Figure 4: Connection schematics for PoE

Powering by 24 V

1. Connect the M12-X RJ45 cable to the device and to your computer or switch
2. Connect the M12-A cable to the device and to the adapter, and plug in the 24 V power adapter
3. Alternatively, connect the M12-A cable to the device and the open-end wires to the 24 V DIN rail adapter

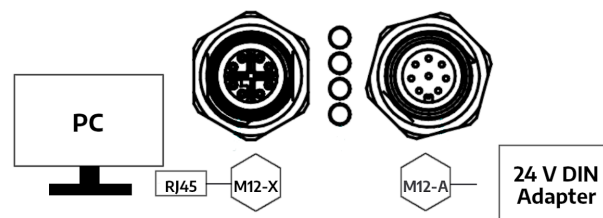


Figure 5: Connection schematics for 24 V power using DIN rail adapter

External Grounding

Safety purposes

The body of the device is constructed from conductive materials: aluminum and carbon. These materials are coated with non-conductive lacquer or anodized aluminum. However, this doesn't necessarily imply that they serve as effective electrical protective layers. Therefore, relying on them for electrical protection is not assured.

Equipotential bonding is made to protect operators against electric shock. It does not allow two different device's chassis to have different voltages on them. Connecting these chassis with a conductive wire will bring those chassis to the same voltage potential and protect the operator against electric shock (and protect against ESD as well). Voltages of both chassis will be equal and the operator won't get hurt by touching both of those devices at the same time.

The point of equipotential bonding is the ground terminal of the building. This is because the Electrical network is (in TT, TN, TNC, and TNC-S cases) tied to the ground. If a dangerous voltage appears on the device chassis, the error current will flow through the ground fault circuit interrupter (GFCI) and switch off the voltage.

EMI reduction

Even though grounding and bonding our sensor is not primarily made for EMI (Electromagnetic interference) reduction purposes, in certain cases, it can improve the EMI behavior of the device. The idea is that the conductive chassis will form a

Faraday cage, which will lead the induced current by a path of the smallest impedance to the ground (it is assumed that the intrusive device is connected with the ground directly or by chassis capacity).

To achieve the smallest impedance, we should follow these rules.

- The grounding wire must be as straight as possible.
- The grounding wire should not be tangled. If the scanner should be moving during the operation, make a half loop only to relax cable bending stress.

Try to use a star topology by connecting the grounding wire of our device directly to the grounding point. Avoid connecting multiple sensors in series.

Avoid ground loops (chassis ground connected in more than one point, for example, the cable shielding and the chassis ground) as they can form a loop antenna and pick up unwanted noise more effectively. If so, the chassis ground should be disconnected at one point to break the loop.

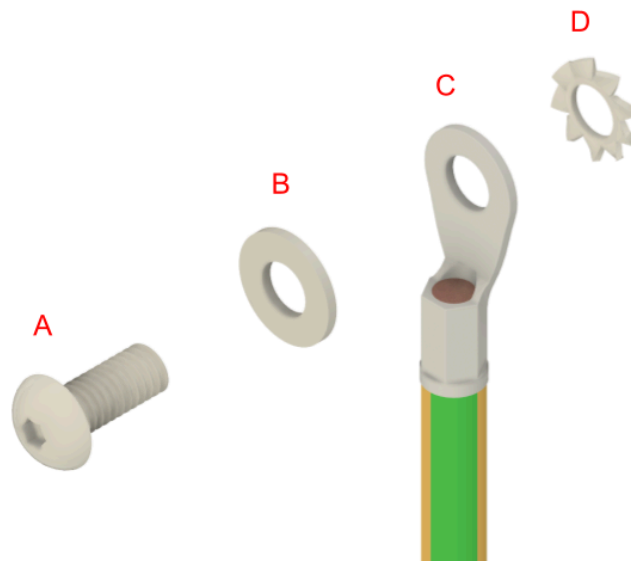
Avoid long or tangled grounding wires. They have higher inductance (and therefore impedance) and are not able to ground high frequencies properly. They can even worsen the EMI.

Required tools:

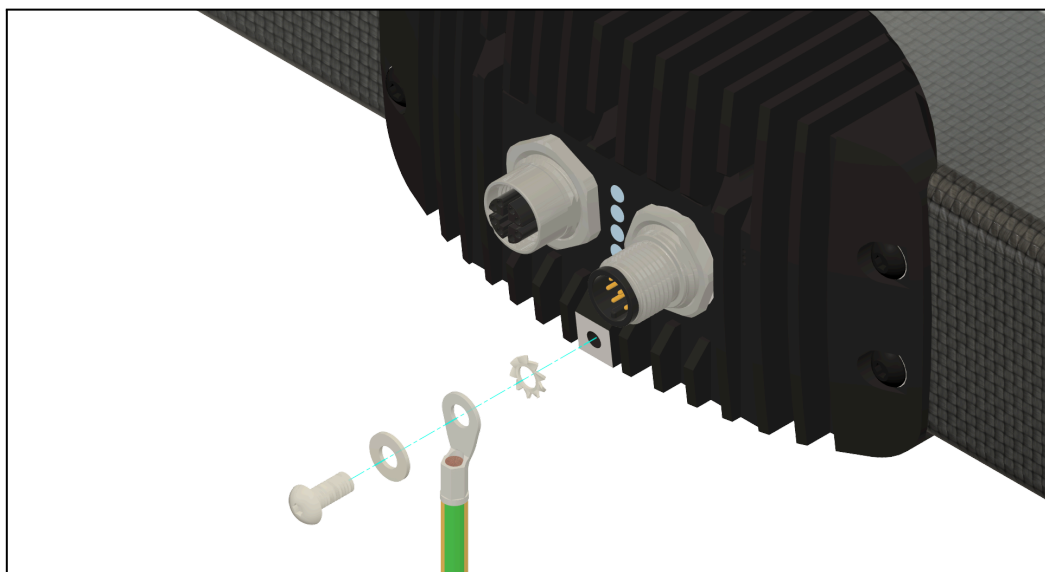
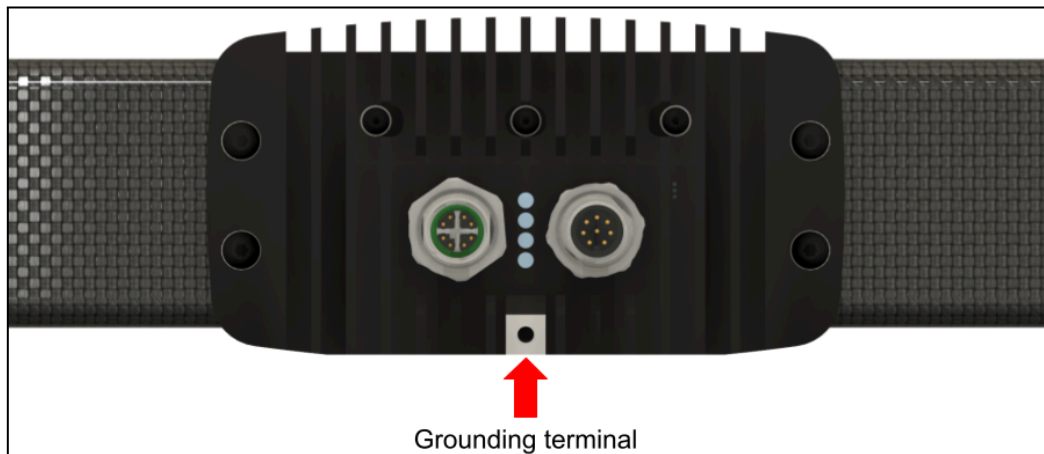
- 1x Screw M4X10mm (A) - The screw must be long enough to hold washers and lug, but not too long since the hole is blind and has limited depth.
- 1x Flat washer (4mm hole) (B) - it will make a hard support for a soft cable lug. It will improve the contact quality.
- 1x Cable lug (4mm hole) © - 2.5-6mm cable (according to the cable used). Lug will manage a good contact between our device and the cable. Lug cable size must be chosen properly, otherwise, the cable won't be holding well, and the contact will be poor.
- 1x Fan washer (4mm hole) (D) - this one will bite through aluminum anodization and make good conductive contact.
- A screwdriver that will fit the used screw-head.
- Lug/cable crimping tool.
- AWG11 Copper-stranded wire of the required size (the shorter the better). Use yellow/green stripe-colored wire, as this is the color of a protective conductor according to the IEC 60446 standard.

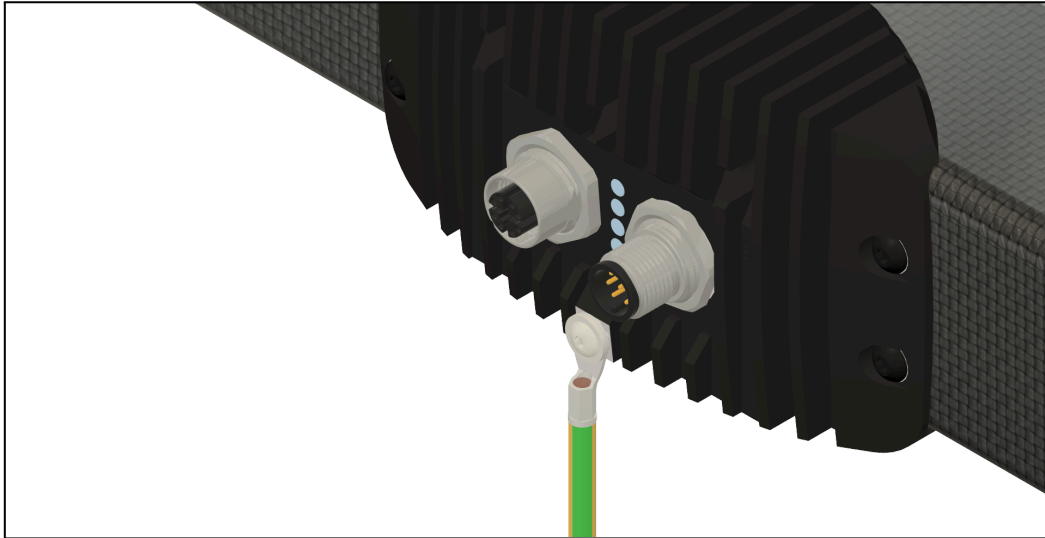
Instructions:

- Crimp the lug on the cable, and prepare the screw and washers according to the picture. The fan washer will be in between the scanner and the lug. Its purpose is to bite through the anodized layer and make good contact.

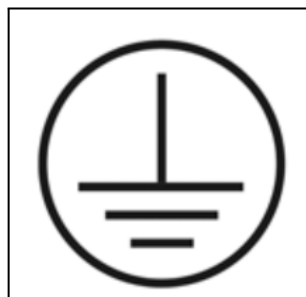


- Here is the place where the *Grounding terminal* is located. Older devices do have this terminal covered with an anodized layer (therefore it is black, not silver).





- Tight the screw at the recommended 1.3 Nm moment. The cable lug should not be able to rotate. Do not over-tighten the bolt, or the thread in the aluminum body might get damaged.
- Connect the device to the grounding terminal in the building. Protective ground should be marked with the following symbol.



Protective ground symbol

Status LEDs

#	LED Name	Color	Description
1	POWER	 Green Red Off	Power ON and OK Power ON, power on the processing unit not OK No power
2	STATUS	 Green Orange Red	Firmware ready Device occupied HW fault
3	ETH1	 Flashing green Green Off	Activity on the link No activity on the link Link is down



Figure 6: Status LEDs of a device working correctly

Supported Network Topologies

The following network topologies are supported by the Photoneo 3D sensors:

- Direct connection to a computer

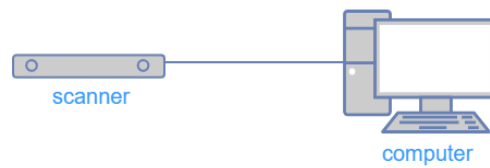


Figure 7: Direct connection

- The sensor connected to a switch

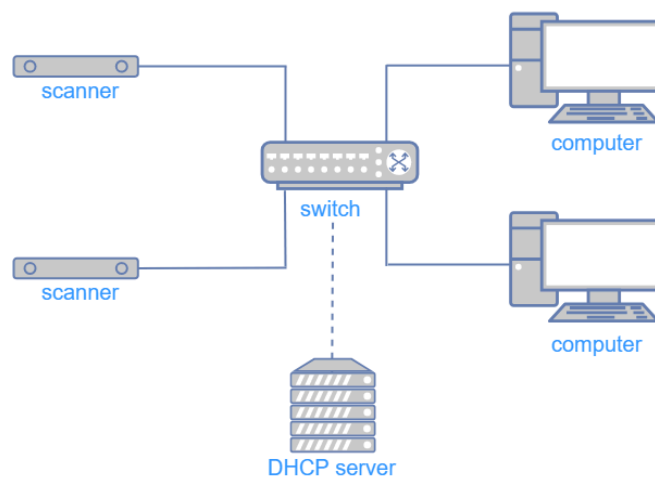


Figure 8.1: Connected to a switch

The following network topology is not supported by the Photoneo scanning device:

- The sensor is connected to a router:

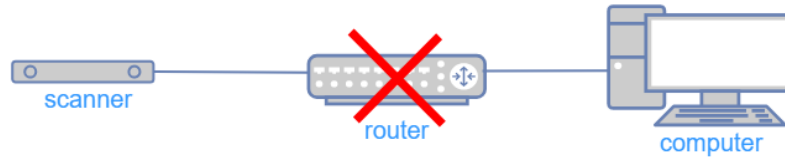


Figure 8.2: Connecting the scanner through a router is not supported

Note:

- Connecting to the scanner via WiFi is not recommended as it is slower and less reliable.

NOTICE

If several 3D sensors are connected to a computer with several Ethernet adapters, using static IP addresses on different subnets is recommended.

Mounting Restrictions

Using external casing for additional Ingress Protection

To protect the device from harsh environmental conditions (high/low temperatures, dust, water jets), it is possible to use an external enclosure.

See the instructions for the IP67 enclosure developed for Photoneo 3D Sensors at [IP67 enclosure](#)

The effect of the additional (planar) optical element (glass) in front of the device can be split into

- a small translation of the point cloud towards the scanning device when compared to the case without the presence of the additional optical element,
- a distortion, which is in most practical cases negligible.

Displacement characterization (for a glass of 3 mm thickness)	Scanner Model			
	S	M	L	XL
Translation [mm]	1.140	1.140	1.127	1.124
RMSQ of distortion [mm]	0.090	0.088	0.088	0.092
Max. distortion [mm]	0.216	0.220	0.208	0.202
Max. local relative distortion [promile]	1.9	1.4	0.7	0.4
Max. local rotation [angular minute]	9.5	6.3	3.5	1.9

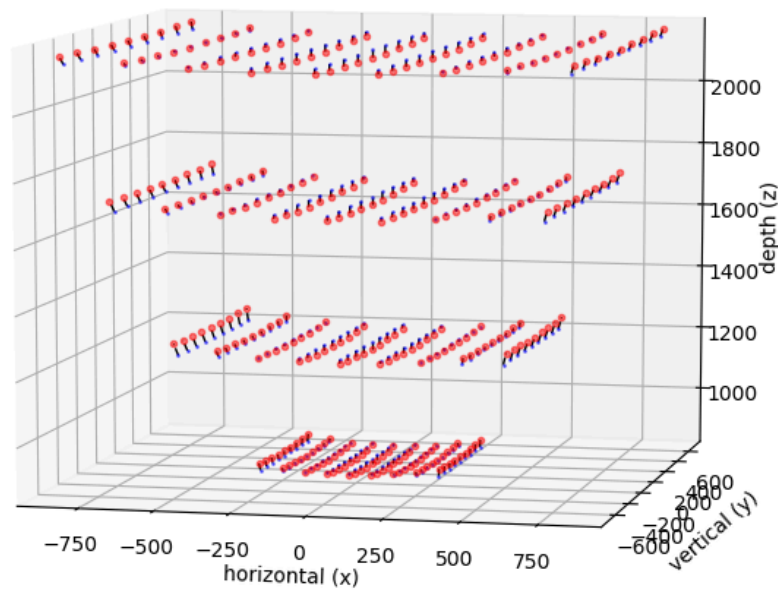


Figure 9: Point cloud distortion for scanner L with casing magnified 200 times (thickness = 3.0mm)

Movement During Scanning

In general, MotionCam-3D (Color) can be mounted on moving constructions or robotic arms, as it can capture dynamic scenes as well as static scenes. The device itself, as well as the scenes, can be in motion or vibrating.

It is possible to mount the PhoXi 3D Scanner on moving constructions or robotic arms, however, it is necessary to stop the movement during the acquisition. Movement of the scanner during the projection of light patterns causes a loss of quality and interferes with depth calculation. Make sure the device and the scanned area are still during the acquisition.

If vibrations are present, use a damping apparatus to isolate the scanner's mounting from the source of the vibrations. Acceleration and deceleration forces according to the scanner's environment restrictions should be taken into account when designing the mount for the scanner. The maximum acceleration allowed during operation (not including the scanning process) is up to 20 ms^{-2} .

Strong Electric Field

As a general rule, always isolate low-voltage, logic-type devices such as Photoneo 3D Sensors from devices that are high voltage and generate high electrical noise. Carefully consider the routing of the wiring for the devices in the panel as well. Avoid placing low-voltage signal wires and communication cables in the same tray with AC power wiring and high-energy, rapidly-switched DC wiring.

Clearance for Cooling and Wiring

Photoneo 3D Sensors are designed to be cooled via natural convection cooling. When designing a mount or an enclosure, refer to the CAD models available at <https://www.photoneo.com/downloads/device-resources/> to ensure you use the up-to-date device dimensions.

CAUTION

In order to ensure adequate cooling, a clearance of at least 25 mm around the device must be allowed. When planning the placement of the Photoneo 3D Sensor, consider placing heat-generating and electronic-type devices in the cooler areas. By reducing exposure to high-temperature environments, you can extend the operating life of electronic devices considerably.

CAUTION

To ensure optimal performance of Photoneo devices, maintain proper ventilation and unobstructed airflow. This is crucial even within the recommended temperature range (refer to device datasheets for specific temperature limits). Inconsistent or blocked airflow may cause the device to enter a cooling mode in extreme cases, temporarily stopping recordings to prevent overheating.

NOTICE

It is recommended to mount the device on a metal plate that will act as a thermal bridge and dissipate the heat produced by the processing unit away from the scanner.

Turning Off the Device

Before turning off the device, make sure it is not actively scanning - the device is not projecting laser patterns. Turn it off by unplugging it from the power.

NOTICE

It is not recommended to unplug the device from the power while it is actively scanning. This is to prevent possible damage to the projection unit.

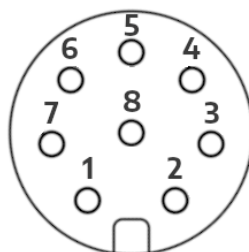
Laser Safety Interlock

NOTICE

Not all devices have the Laser Safety Interlock feature. This feature must be enabled per request at Photoneo premises before shipping.

To operate the device, it is necessary to supply a high signal (5 - 24V) on the Pin 8 (OPTO_IN2) on the 24V connector. If no power is present (low signal) on Pin 8 (OPTO_IN2), the projection unit will not emit light.

Please, refer to the [Powering the Device & Data Connection](#) subsection for full powering instructions. Laser Safety Interlock can be used in combination with PoE or 24V powering.



24 V connector - view from the mating side

Wire number	Color	Function
1	White	DC_IN:+ 24 V
2	Brown	OPTO_IN2_GND: laser interlock ground
3	Green	ground
4	Yellow	-
5	Grey	-
6	Pink	-
7	Blue	-
8	Red	OPTO_IN2: laser interlock signal 5 - 24 V

Configuration

Photoneo sensors can be operated via a dedicated application - PhoXi Control or other GigE Vision-compatible 3rd party applications. PhoXi Control application enables users to control Photoneo 3D Sensors manually via a GUI or by a computer program using the provided API or GenICam interface. Alternatively, Photoneo sensors can run in GigE Vision compatible mode in which PhoXi Control cannot be used.

PhoXi Control

The GUI is primarily used to set up the scanning environment, configure advanced scanner parameters, and visualize the output. In addition, the GUI can also be used as a powerful debugging tool for development with the API. Calls to the API trigger the same response in the GUI as user inputs. After triggering the scan by calling the API method, the application will execute the scan, send it as an output of the call, and display it simultaneously in the GUI.

The API serves as a central platform for building custom applications for Photoneo 3D Sensors. In order to facilitate the development process and reduce computing demands, all computations are performed on the device itself.

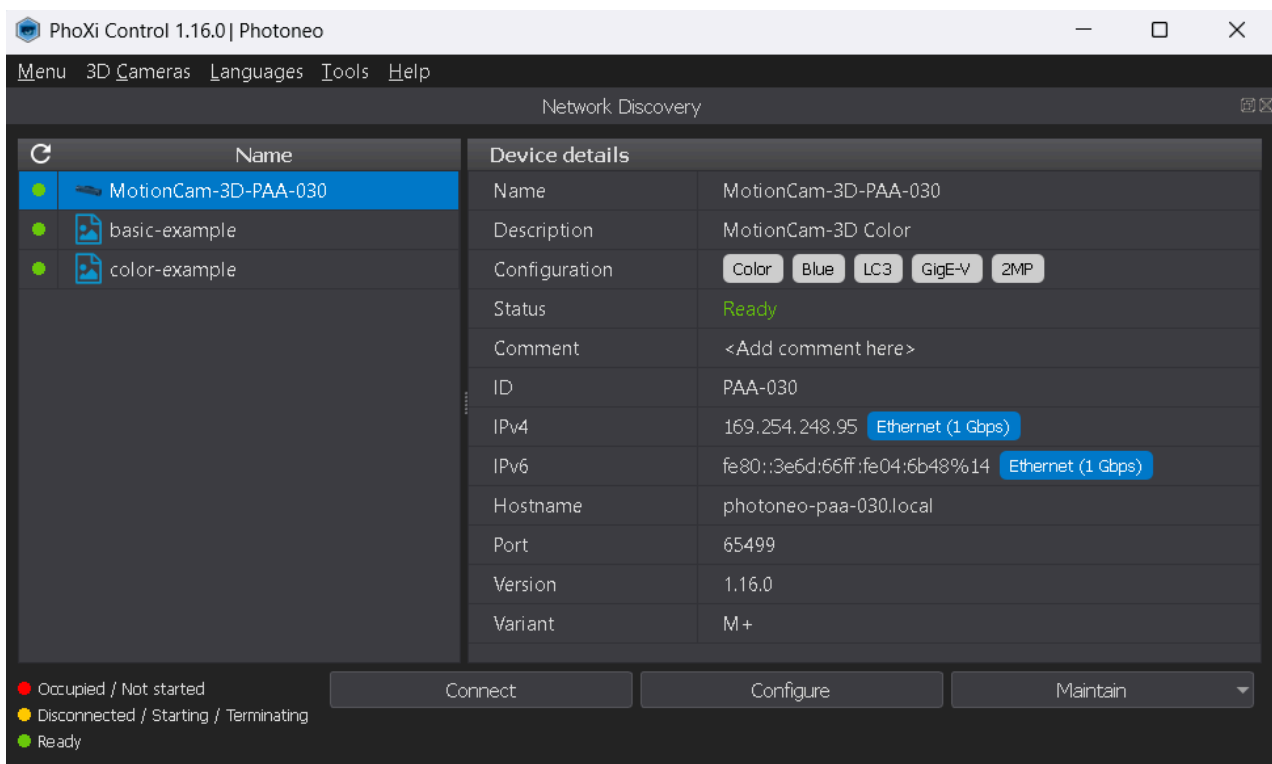


Figure 10: PhoXi Control – Network Discovery

GenICam interface (Discontinued)

The Generic Interface for Cameras standard is the base for plug-and-play handling of cameras and devices. It was developed by the European Machine Vision Association (EMVA)

GenICam support is provided via the GenTL library that works as a wrapper around the PhoXi Control C++ API. PhoXi Control has to be running to use the GenICam interface.

You can download the latest version of PhoXi Control and the PhoXi Control User Manual from our website at <https://www.photoneo.com/downloads/phoxi-control/>. User guides for [GenICam integrations](#) contain more detailed information and requirements for running the examples.

GigE Vision

GigE Vision is a high-speed communication protocol and interface standard that is designed for transmitting data over Ethernet networks. Third-party software with GigE support can be used to operate Photoneo 3D Sensors without a running instance of PhoXi Control.

User guides for [GigE integrations](#) contain more detailed information and requirements for running the examples.



To enable or disable GigE Vision functionalities, download and install the necessary utilities from the provided corresponding links:

- GigE Vision utilities for Windows: www.photoneo.com/dl/gigev-utils-win
- GigE Vision utilities for Linux: www.photoneo.com/dl/gigev-utils-lin

Hardware Parameters

Powering the device

The following subsections explain different options for powering a Photoneo 3D Sensor. In case both the PoE and 24 V connector (M12-A) are used to power the device, PoE is prioritized.

Power Over Ethernet Connector

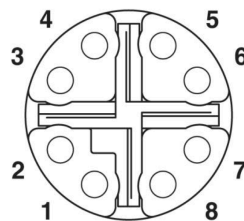


Figure 11: PoE connector pinout, view from the mating side

Connector type: M12 X coded, 1404741

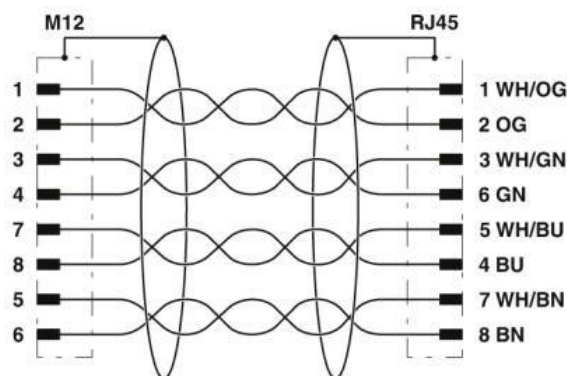


Figure 12: Contact assignments of the M12 and RJ45 plug

Powering Requirements

PoE Standard	IEEE802.3at
Operating voltage U_e DC	min. 55 V
Residual ripple maximum (% of U_e)	0.5 %
Rated operating current I_e (I_{max})	0.360 A (0.6 A)
Minimum Power	33 W
Shielding	Fully Shielded RJ45

Transfer data rate	1 Gbit
Maximum recommended cable length	20 m (wire cross area 0.14 mm ²)

24 V Power Connector (M12-A)

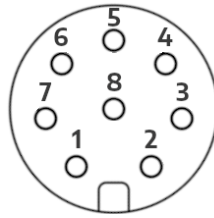


Figure 13: 24 V Power & GPIO pinout, view from the mating side

Connector type: M12 A coded, M12A-08PMMP-SF8001

Pin	Pinout	Function
1	DC_IN	+ 24 V
2	OPTO_IN2_GND	*laser interlock ground
3	GND	ground
4	OPTO_IN1	hardware trigger input signal (5 - 24 V)
5	OPTO_IN1_GND	hardware trigger input ground
6	OPTO_OUT	hardware trigger output signal (5 - 24 V)
7	OPTO_OUT_GND	hardware trigger output ground
8	OPTO_IN2	*laser interlock signal (5 - 24 V)

* Laser interlock safety feature must be enabled per request at Photoneo premises before shipping.

Powering Requirements

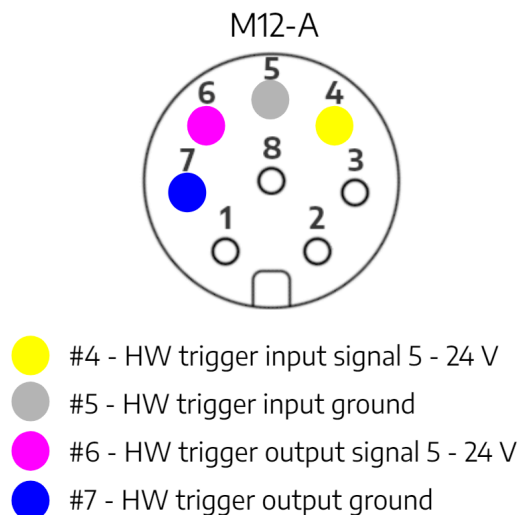
Operating DC voltage U_e (U_{min} - U_{max})	24 V (20 - 30 V)
Residual ripple maximum (% of U_e)	2 %
Rated operating current I_e (I_{max})	1 A (2 A)
Minimum Power	60 W
Maximum recommended cable length	20 m (wire cross area 0.25 mm ²)

Hardware Trigger Characteristics

Hardware trigger provides the user with means of triggering devices by external means - outside of the software environment. More information on the software configuration can be found in the [PhoXi Control User Manual](#). This functionality is mostly used for synchronization purposes:

- With external events, such as an object arriving inside the field of view of Photoneo 3D Sensor (i.e. triggered by an optical gate)
- With other devices, such as 2D cameras, PLCs, ...
- With multiple Photoneo 3D Sensors

The hardware trigger is activated by feeding a logical signal to the specified pin of the M12-A connector. The device is also able to signal that it is currently acquiring → this signal can be read from the output pin on the M12-A connector.



View of the port on the Photoneo 3D Sensor (similar to the previous figure)

The allowed input signal voltage range is 5 - 24 V, depending on the user's requirements. The output signal needs to be read through a pull-up resistor.

To correctly connect/wire the devices together, please adhere to the following schematics for trigger input and trigger output.

Trigger Input

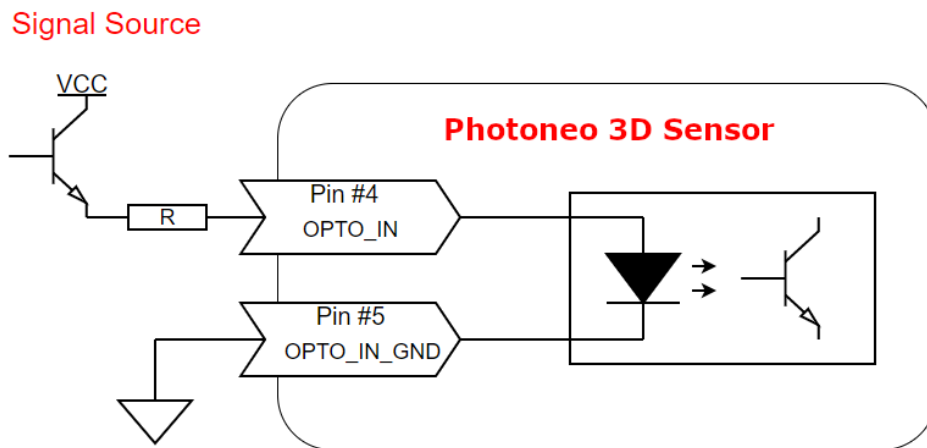
Circuit Characteristics

Both wiring schematics below are valid. It is recommended to

- Use $R = 0 \Omega$ if your $VCC = 5 - 12 V$
- Use $R = 4k7 \Omega$ if your $VCC = 24 V$

The trigger input can be done as a common cathode or common anode. Refer to the diagrams below.

Common Cathode



Common Anode

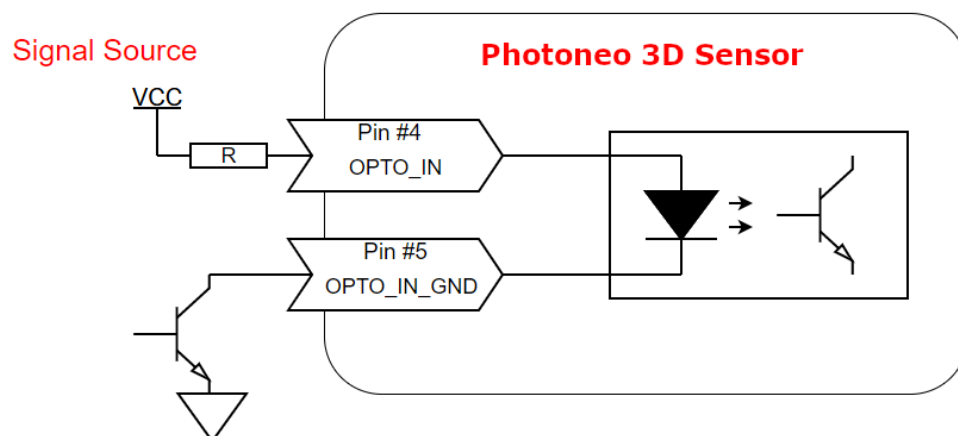


Figure 14: Trigger input wiring options

Input Signal Characteristics

The trigger input signal causes the device to start the acquisition. In the case of MotionCam-3D the trigger input signal is a transition between logic zero and logic one. Therefore the signal can be:

- Falling edge → change from logic 1 to logic 0
- Rising edge → change from logic 0 to logic 1

The choice of the signal depends on the specifics of the setup. For example, the setup for a falling edge can be:

- The input pin is kept at 24 V and it's lowered to 0 V to produce the falling edge
- The input pin is kept at 0 V and it's elevated to 24 V for a short period of time. Letting it fall back down produces a falling edge that triggers the device

Whether the device is triggered by a falling edge, rising edge, or both is controlled by a parameter called Hardware Trigger Signal.

Trigger Output

Circuit Characteristics

The trigger output is read through the VCC pull-up. Please refer to the diagram below. It is recommended to

- Use a $R = 10k\ \Omega$ resistor to read the signal (for example using a PLC)
- Use a $R = 1k6\ \Omega$ resistor when the MotionCam-3D is daisy-chained with another MotionCam-3D and your $VCC = 5 - 12\ V$
- Use $R = 4k7\ \Omega$ resistor when the MotionCam-3D is daisy-chained with another MotionCam-3D and your $VCC = 24\ V$

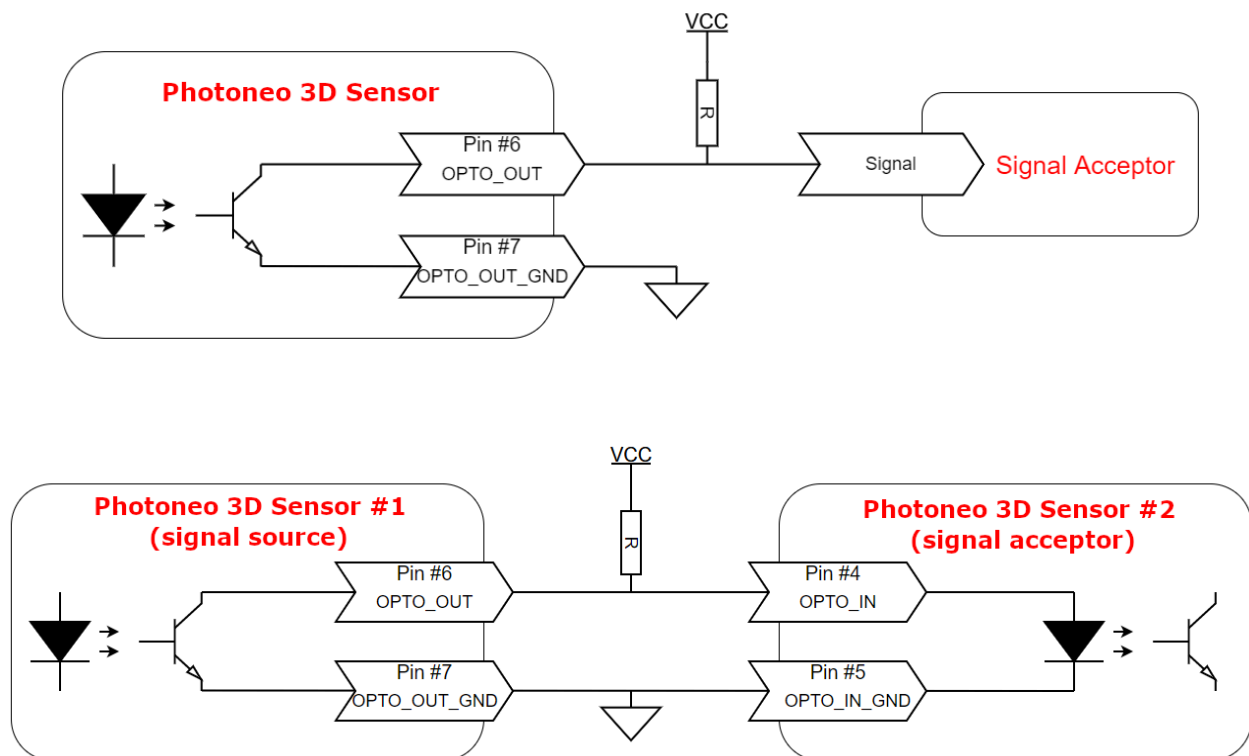


Figure 15: Recommended wiring for trigger output

Output Signal Characteristics

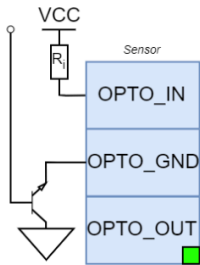
The trigger output signal is used to mark the time during which the device is in acquisition. Once the acquisition starts, the signal changes from logic 0 to logic 1. After it finishes, it changes from logic 1 to logic 0.

The acquisition is defined as follows:

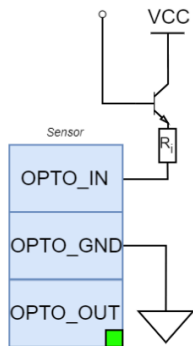
- In camera mode → the time during which the laser sweeps the scene and the 3D data are gathered.
- In scanner mode → the time it takes to project all necessary patterns as well as LED texture.

Simplified wiring schemes

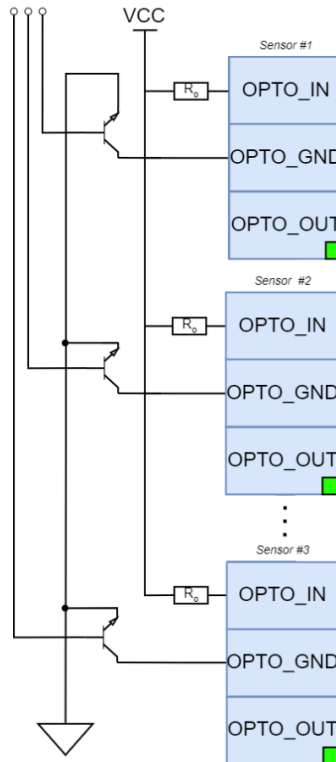
SEXT A



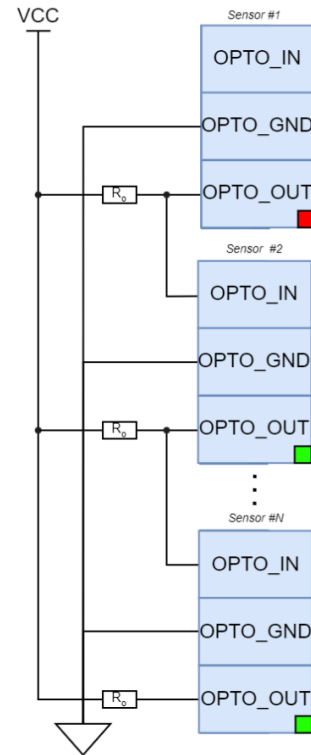
SEXT B



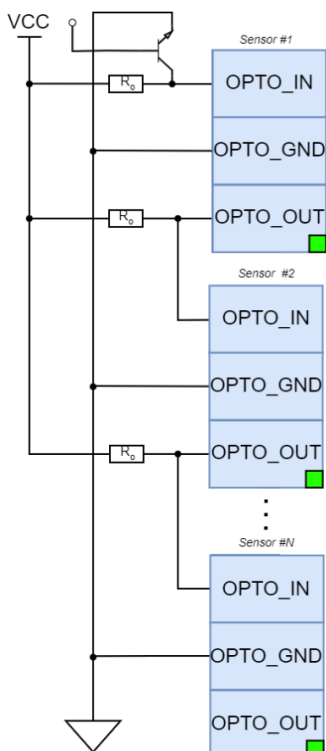
MEXT



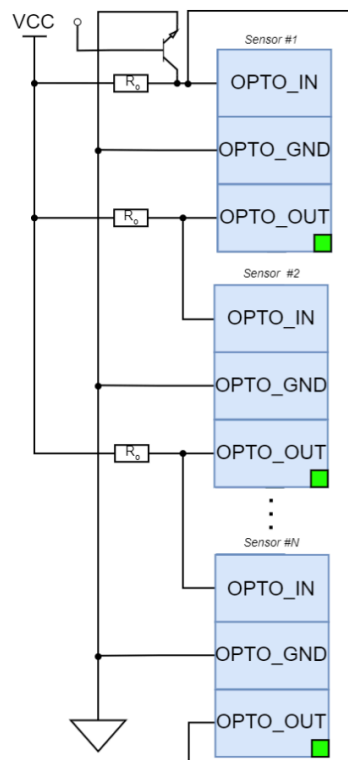
INTSEQ



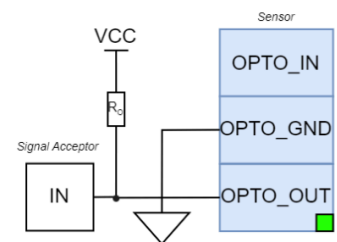
EXTSEQ



EXTDCL



OUT



 HW trigger = TRUE; Freerun = TRUE
 HW trigger = FALSE

SEXT A	Single device triggered by HW trigger - Common Cathode
SEXT B	Single device triggered by HW trigger - Common Anode
MEXT	Multiple devices triggered by HW trigger independently from each other
INTSEQ	Two or more devices triggered sequentially in a daisy chain - triggered by the Sensor #1
EXTSEQ	Two or more devices triggered sequentially in a daisy chain - Sensor #1 triggered externally
EXTDCL	Two or more devices triggered sequentially in a loop - daisy chain in a loop
OUT	Photoneo 3D Sensor outputs a signal to another device (Signal Acceptor)

*Resistors R_i and R_o are dependent on the voltage of the power source and type of the connected devices - refer to the sections [Trigger Input](#) and [Trigger Output](#).

Ground pins OPTO_IN_GND and OPTO_OUT_GND can be connected to the same ground (of the voltage source) - in this case, OPTO_GROUND (separate from the ground of the sensor itself).

Projection Unit Properties

Projection unit type	Laser Class 2 - Red	Laser Class 2 - Blue	Laser Class 3R - Red	Laser Class 3R - Blue
Light source	Visible red light (laser)	Visible blue light (laser)	Visible red light (laser)	Visible blue light (laser)
Laser class	2	2	3R	3R
Wavelength	637 nm	440-455 nm	640 nm	440-455 nm
Pulse energy	18.6 μ J	72 μ J	300 μ J*	89 μ J*
Pulse length	1 ms	5.0 ms	5.3 ms	5.3 ms
Projection width horizontal	47.5° $\pm$ 1°	47.5° $\pm$ 1°	47.5° $\pm$ 1°	47.5° $\pm$ 1°
Projection width vertical	36.0° $\pm$ 2°	45° $\pm$ 1°	36.0° $\pm$ 2°	45° $\pm$ 1°

*Depends on the specific model. Contact our [Help Center](#) for more information.

Make sure to check the values found on the back side of your Photoneo 3D Sensor for the exact parameters.

Note: Contact our [Help Center](#) or your Photoneo Sales Representative to get more information about the projection unit types that are available for the requested model.

Environmental Conditions

Transport

Ambient temperature	From -20 °C to 50 °C (max gradient 10 °C/hour)
Humidity	From 0 % to 95 % non-condensing
Atmospheric pressure	From 1080 hPa to 660 hPa (corresponding to an altitude of -1000 m to 3500 m)

⚠ CAUTION

Please ensure that the device is always transported in its original casing or that it is properly cushioned for transport.

Operation

Operating temperature for optimal scanning performance	From 22 °C to 25 °C
Overall operating temperature	From 0 °C to 40 °C
Humidity	From 0 % to 95 % non-condensing
Atmospheric pressure	From 1080 hPa to 660 hPa (corresponding to an altitude of -550 m to 3500 m)
Maximum acceleration (idle)	20 ms ⁻²

NOTICE

For the correct performance of the device, make sure it has reached its operating temperature. The operating temperature is reached approximately after 45 minutes of the device being powered up or after 10 minutes of continuous scanning in the free run mode, followed by 2 - 5 minutes of cool down to stabilize the temperature.

Degree of Ingress Protection

Photoneo 3D Sensors have the following mechanical protection according to standard EN 60529:

- IP65 Mechanical Protection
- Completely protected against the ingress of dust (dust-tight).
- Protected against low-pressure jets of water from any direction.

Cleaning Instructions

The optical scanning device produced by Photoneo is technically advanced yet a low-maintenance device. To preserve the performance and quality of the scanning, please check and maintain its outer optical parts regularly.

The glasses covering the camera unit and the projection should not be touched by bare hands to avoid staining the glass. This could interfere with light passing through them. If the glass was touched or lightly stained by any other mechanism, wipe the glass with lint-free wipes intended for optical components.

In cases where the device is used in an environment with lots of dust, especially when the dust contains sharp or hard particles that could potentially damage the glass, clean the glasses with a specialized cleaning solution for optical components, e.g.: First Contact™ Cleaning Solution².

To clean the glasses:

1. Coat the glass with the solution using the applicator. Make sure not to spread it to the edges. The solution immediately dries and creates a film over the glass.
2. Remove the film from the glass using peel tabs with wooden or plastic tips.
3. The film removes any dirt or particles from the glass.

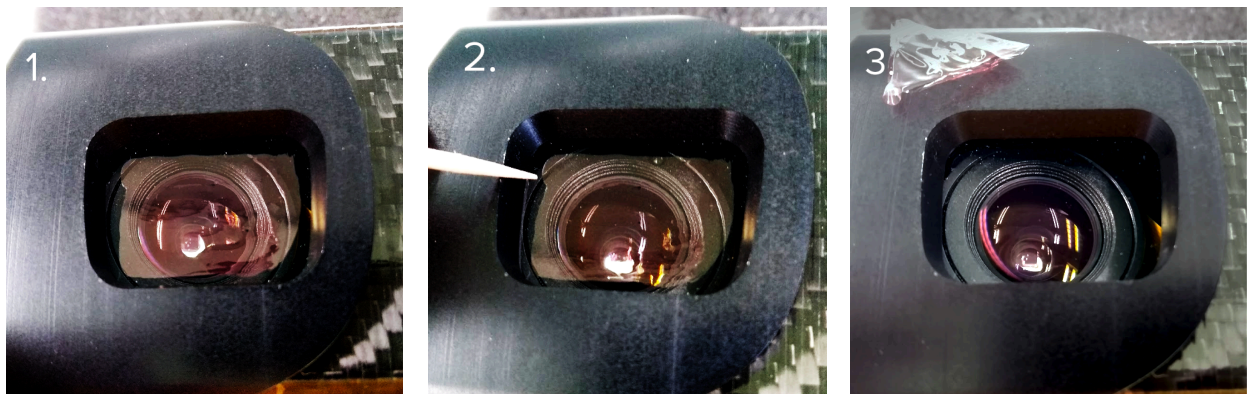


Figure 16: Cleaning process of the glass over the camera unit

² www.photoniccleaning.com/product-p/rfcr.htm

Scanning Parameters

Information about the scanning range and parameters of your Photoneo 3D Sensor is available in the device datasheet. Full user manual, datasheets, CAD models, and other instructions are available:

<https://photoneo.com/downloads/device-resources/>

Datasheet Parameter Definitions

The datasheet defines several performance properties of a Photoneo 3D Sensor. A population of production devices is characterized by the typical and maximum observed values, given a properly maintained device. The typical value represents the performance of the average device, while the maximum value is the upper limit of the population. Some of the performance properties were determined theoretically from a model.

The table values represented in the datasheet are the maximum values. The graphs show both maximum and typical values.

Standard Conditions

The *Standard Conditions* refer to a stable environment for measurements, characterized by homogenous ambient light, excluding strong or flashing light sources other than the verified device, a stable humidity and stable room temperature (ISO 554), and the absence of shocks or shaking.

3D Sensing Technology

Photoneo 3D Sensor either uses sequential structured light technology or Parallel Structured Light Technology. More information can be found in the section [Objects Suitable for Scanning](#) of the Photoneo 3D Sensors - User Manual.

Output Data

Depending on the device used for scanning, the output data structure can differ.

- 3D points (x y z)
 - a. Floating numbers depicting the position of a 3D point in a given coordinate frame. The default coordinate frame has its origin in the 2D camera with the Z-axis towards the scene, the X-axis continuing to the right of the device, and the Y-axis facing downward.
- Normals (x y z)
 - a. The normal vector for each 3D point can also be calculated. The normal vector is perpendicular to the area surrounding the point.
- Depth Map (z)
 - a. The “depth” of a point is the absolute 3D distance from the image sensor to the measured point (the ray of light that hits the surface of the object). The DepthMap is, therefore, always in the camera coordinate system and corresponds to the Z coordinate value in the point cloud.
- Color Image (RGB)

- a. A 2D RGB texture is available on the MotionCam-3D Color and PhoXi 3D Scanner Gen3 at different resolutions.
- Texture (grayscale/RGB)
 - a. A 2D texture (LED, Computed, Laser, Focus, Color).
- Confidence (float)
 - a. For each measured 3D point, the “confidence” value expresses certainty about the accuracy of the point measurements. For example, a confidence value of 0.12 means that the estimated error for a point measurement is 0.12 mm. This value is based on a heuristic method that considers the light conditions for each pixel.

Scanning Distance

Scanning distance is the distance between the sensor and the verification object. It can be expressed in millimeters or simplified into terms such as near, sweet, or far to describe the minimal, ideal or maximal distance of the scanned object from the device.

Point-to-Point Distance

The *Point-to-Point Distance* is the average lateral distance between the closest neighboring points in the point cloud at the specified distance from the sensor. It can also be interpreted as the average diameter of a patch associated with a single 3D point observed at a specific distance from the sensor

Figures 17 and 18 show the point size as a function of the scanning distance. The point size linearly increases with the distance. Therefore, it is possible to calculate the approximate point size using the *Optimal scanning distance (sweet spot)* and the *point-to-point distance (at the sweet spot)* values, which can be found in the datasheet. If P_s is the point size at the optimal scanning distance D_o , then we can calculate the approximate point size P at the desired distance D_d as follows:

$$P = \left(\frac{P_s}{D_o} \right) \times D_d$$

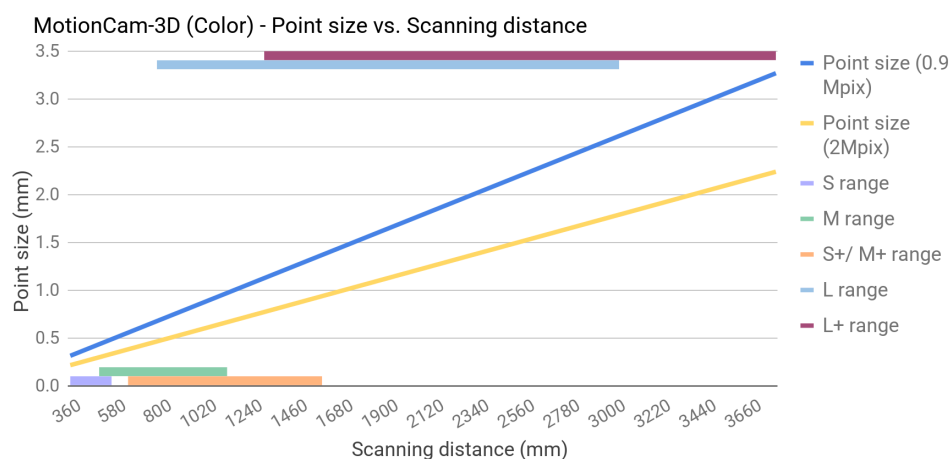


Figure 17: Relationship between scanning distance and point size for the MotionCam-3D (Color) devices

PhoXi 3D Scanner Gen3 - Point size vs. Scanning distance

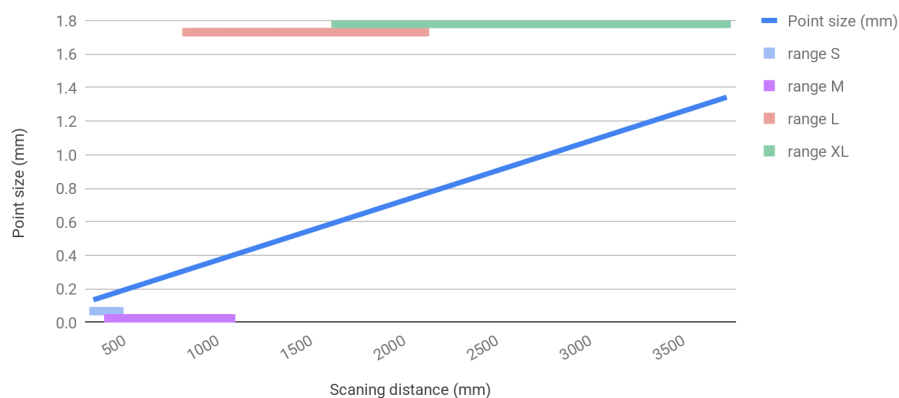


Figure 18a: Relationship between scanning distance and point size for the PhoXi 3D Scanner Gen3 devices

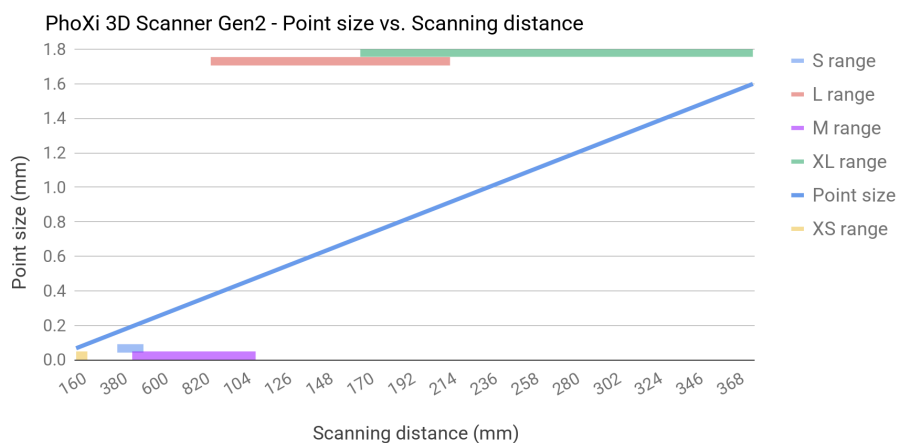


Figure 18b: Relationship between scanning distance and point size for the PhoXi 3D Scanner Gen3 devices

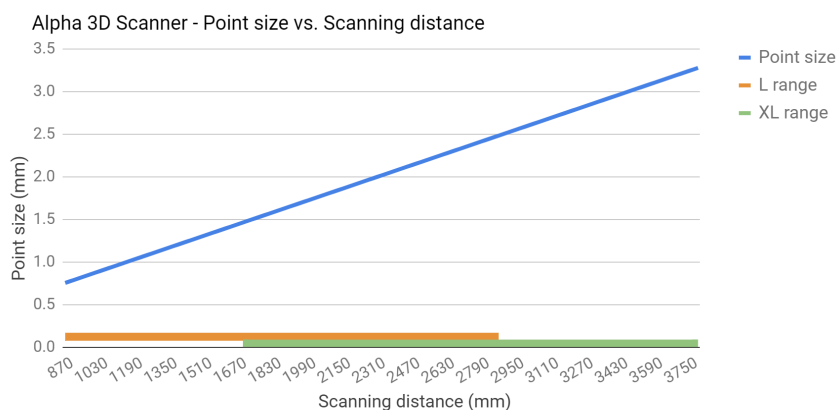


Figure 19: Relationship between scanning distance and point size for the Alpha 3D Scanner devices

Scanning Time

The total *Scanning Time* is the sum of the time required for acquisition, computation, and transfer.

Depth Map Resolution

The *Depth Map Resolution* defines the number of pixels of the primary 2D camera used for 3D sensing.

Color Image Resolution

The *Color Image Resolution* refers to the number of pixels of the secondary RGB camera. The resolution of the RGB camera can be set to one of the predefined values. Note that the *Color Image Resolution* is independent of the *Depth Map Resolution*.

Frames Per Second

The *Frames Per Second* (FPS) expresses the maximum achievable frame rate, i.e., the number of 3D scans per second. The FPS value can be affected by the selected profile or parameters.

Dimensions

The *Dimensions* are expressed in 3 values that represent the length, height, and depth of the device in millimeters, respectively.

Baseline

The *Baseline* is the distance between the primary 2D camera and the projection unit.

Weight

Weight of the device (without accessories).

Temperature Working Range

The *Temperature Working Range* refers to the operational range of temperatures of the Photoneo 3D Sensors. To achieve the optimum scanning performance, the sensor needs to be thermalized within the optimal temperature range (standard atmospheric conditions defined by ISO 554).

Projection Unit Laser Color

The *Projection Unit Laser Color* describes the color of the laser used in the sensor's projection unit. The type of the projection unit can have an effect on the scanning performance on specific scenes and objects.

Power

The device can be powered using a Power over Ethernet injector or a 24V adapter. Further information can be found in section [Powering the Device & Data Connection](#).

Processing Unit

The processing unit for Photoneo 3D Sensors is the NVIDIA Jetson TX2. This unit performs all 3D data computations directly on the device, which helps to reduce external computing demands

IP Rating

Indicates the level of protection against solid particles and liquids, as defined by IEC 60529. The first digit rates dust protection, the second rates water resistance; higher numbers mean greater protection.

For more information, visit : <https://www.iec.ch/ip-ratings>

Data Connection

It is recommended that the device be connected to a 1 Gbit network to ensure sufficient data flow.

Tools for Infield Maintenance

Photoneo 3D Sensors offer a variety of tools for infield maintenance.

- **Maintenance Tool**
 - Supported on MotionCam-3D, MotionCam-3D Color, PhoXi 3D Scanner, Alpha 3D Scanner devices
 - Required pattern - Yes
 - Marker pattern
 - Can be purchased from Photoneo
 - Printing is possible but not recommended as even small scaling printing inaccuracy can lead to incorrect calibration
 - Command line application executable via PhoXi Control GUI and API
- **Marker Dots Correction**
 - Supported on MotionCam-3D, MotionCam-3D Color, PhoXi 3D Scanner, Alpha 3D Scanner devices (shipped after 05-26-2025)
 - Required pattern - Yes
 - 4 or more Marker dots required (must be purchased from Photoneo)
 - GUI, API
 - GigE*
- **Autonomous Maintenance**
 - Supported on MotionCam-3D Color (shipped after 05-26-2025)
 - Required pattern - No
 - GUI, API
 - GigE*

*Limited functionality - feature can be activated without status reporting

Using one or combination of the tools is recommended:

- During system setup, before starting operations
- If the device experienced extensive vibration or physical shock (transport, robot collision)
- After major environmental changes, like a relocation or temperature/humidity fluctuation
- As a part of a precision-focused workflow, where you might want to run a quick check regularly (recommended once or twice a year, or during general system maintenance sessions)

Maintenance Tool

Maintenance Tool is a Photoneo software used to validate 3D Sensors by acquiring a marker pattern, verifying calibration, and adjusting it if needed. It requires a marker pattern printed on a high-quality surface and the device to be running for at least 45 minutes. Detailed manual can be found in *Tools for Infield Maintenance* section in [PhoXi Control User Manual](#).

Marker Dots Correction

Marker Dot Correction is a feature that helps maintain a 3D Sensor's point cloud at a fixed position relative to permanently installed marker dots. It requires a Photoneo 3D Sensor (shipped after May 26, 2025) with Firmware 1.15 or higher, and specific Photoneo marker dots (65x65mm or 140x140mm). Detailed manual can be found in *Tools for Infield Maintenance* section in [PhoXi Control User Manual](#).

Autonomous Maintenance

Autonomous Maintenance is a feature for MotionCam-3D Color devices (shipped after May 26, 2025) with firmware 1.15 or higher and for PhoXi 3D Scanner Gen3, designed to maintain long-term measurement accuracy without manual intervention or external markers. It requires a static scene during calibration checks and the device to be running for at least 45 minutes. Detailed manual can be found in *Tools for Infield Maintenance* section in [PhoXi Control User Manual](#).

For more information on how to use and activate each of the Tools for Infield Maintenance, please check the same name section in the [PhoXi Control User Manual](#).

Compliance with Standards

Photoneo 3D Sensors conform to the following standards and test specifications. Please note that the certification status may change without notification. Consult your local Photoneo representative if you need additional information related to the latest listing of exact approvals.

CE



Photoneo 3D Sensors satisfy requirements and safety-related objectives according to the EC directives listed below. This CE mark is supported by tests conducted by the manufacturer.

Laser Classification

The Laser class of the devices is determined according to EN 60825-1:2014 Equipment Classification and Requirements standard. The laser class was tested by an independent certification body.

Photoneo 3D Sensors are Laser Class 3R or Laser Class 2 devices. All devices are labeled according to their respective class following rules given by the harmonized standard.

Details about the laser device used can be found in the section [Projection Unit](#).

If necessary, please contact Photoneo for a written Declaration of Laser Class for your specific device.

Dimensions and Illustrations

MotionCam-3D Color (Blue)

Bottom View: Mounting Plate

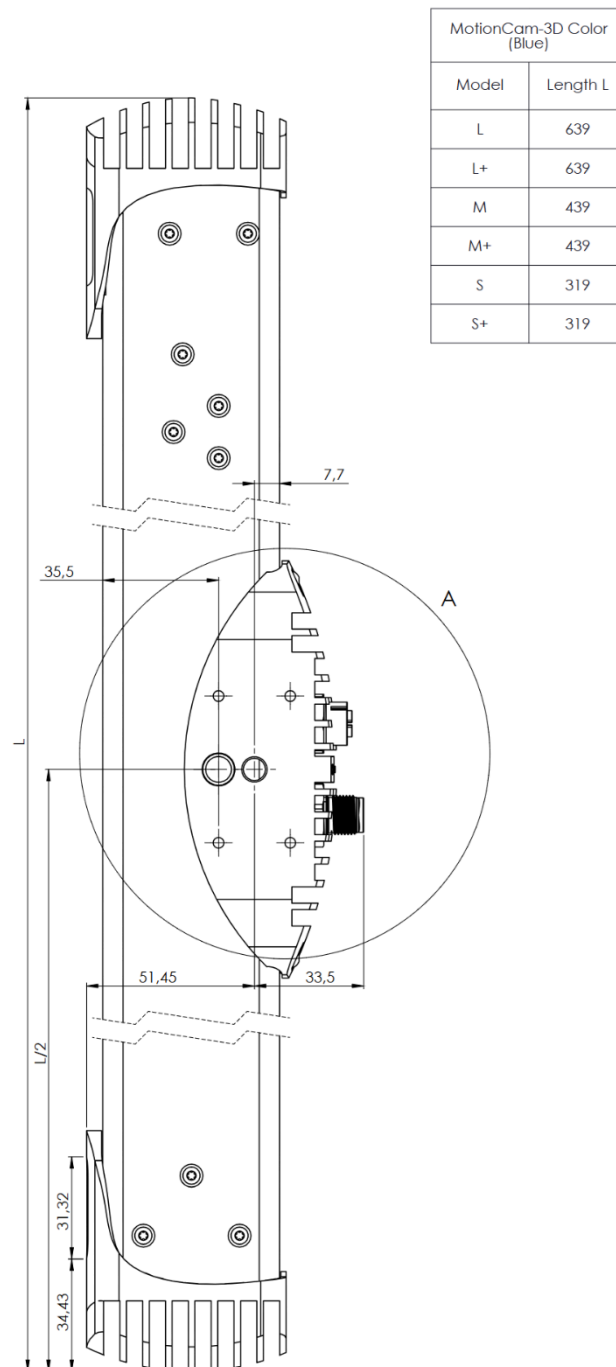


Figure 19: Bottom view of MotionCam-3D Color (Blue)

Bottom View: Detail A

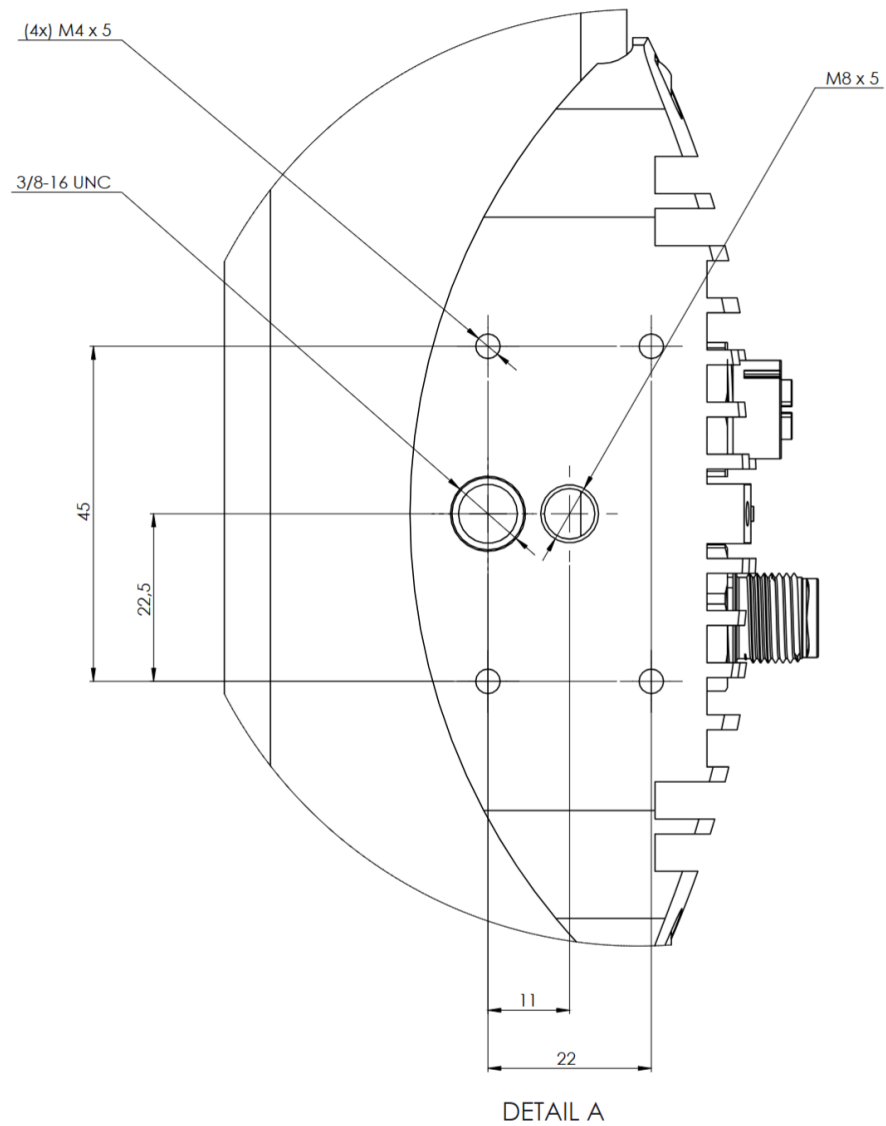


Figure 20: MotionCam-3D Color (Blue) - Detail A

Front View: Projection Unit and Camera Unit

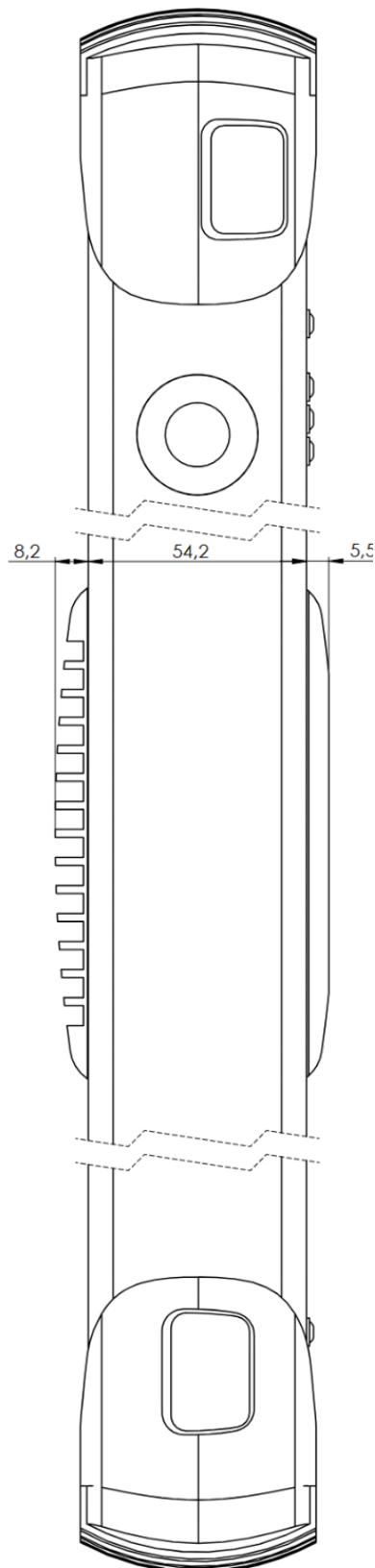


Figure 21: Projection unit and camera of MotionCam-3D Gen 3 Color (Blue)

MotionCam-3D Color (Red)

Bottom View: Mounting Plate

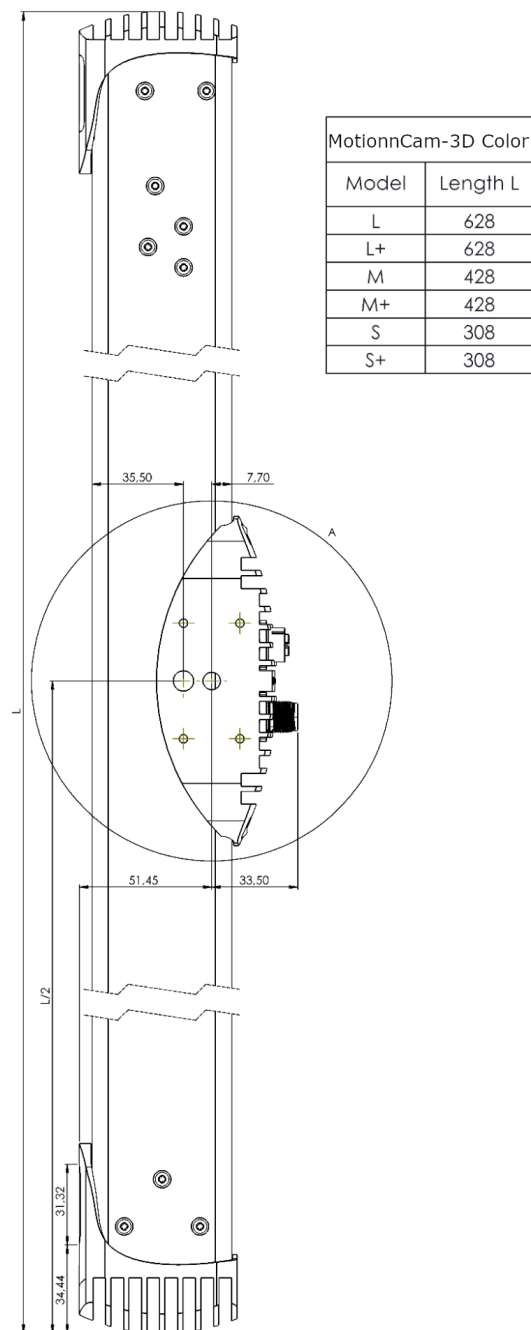


Figure 19: Bottom view of MotionCam-3D Color (Red)

Bottom View: Detail A

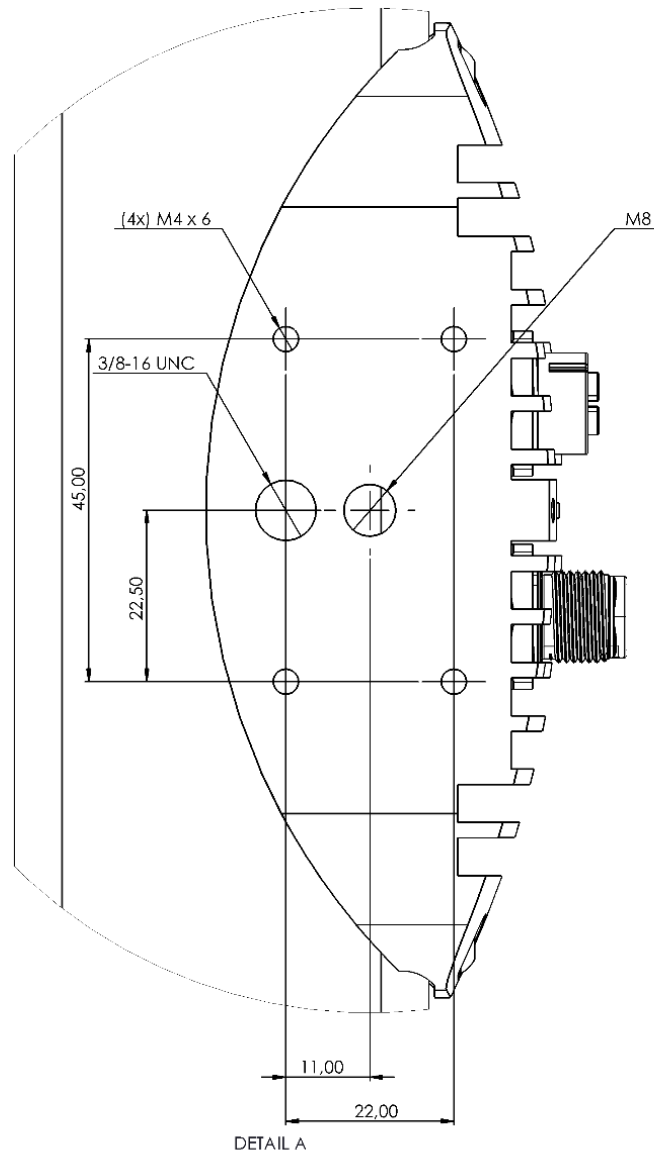


Figure 20: MotionCam-3D Gen 3 Color (Red) - Detail A

Front View: Projection Unit and Camera Unit

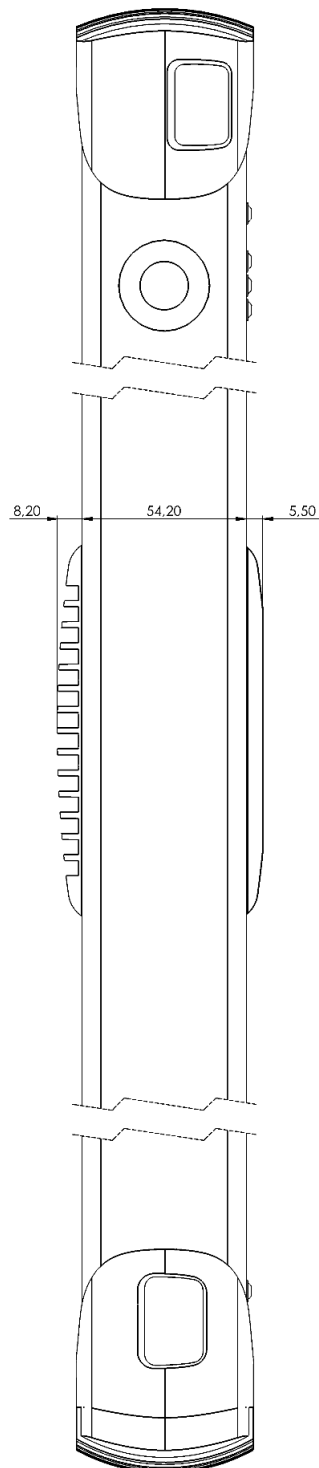


Figure 21: Projection unit and camera of MotionCam-3D Color (Red)

MotionCam-3D Version A

Bottom View: Mounting Plate

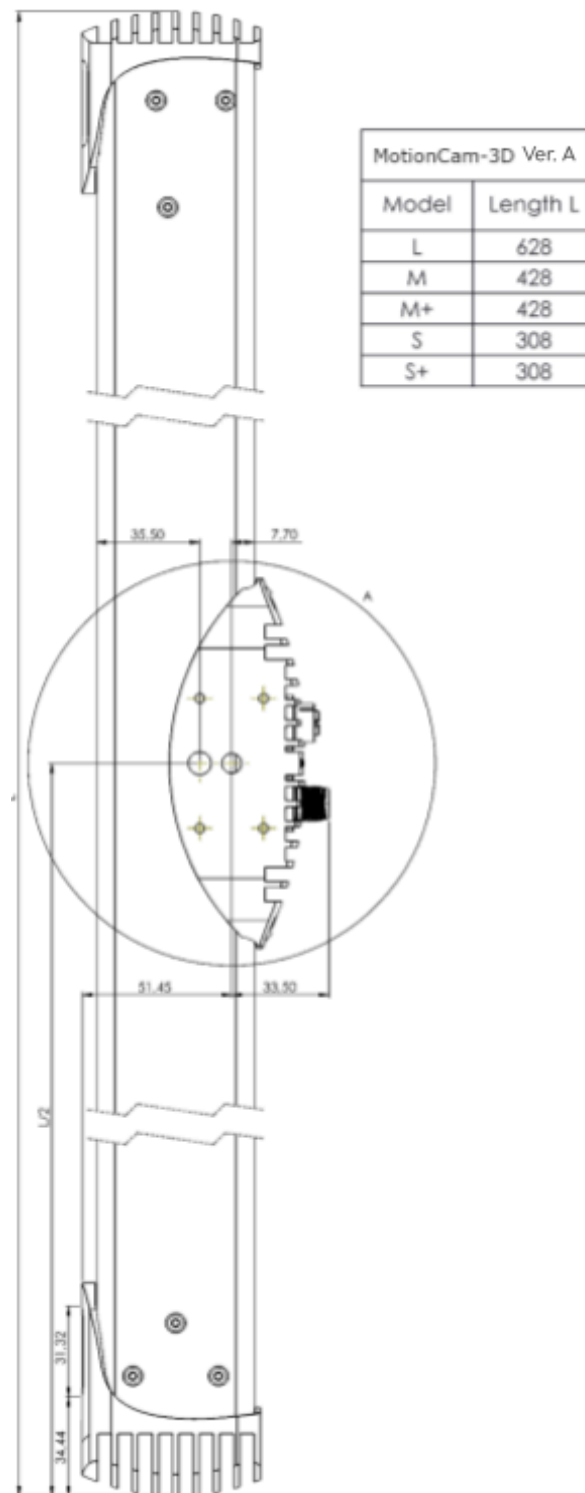


Figure 22: Bottom view of MotionCam-3D Gen 3

Bottom View: Detail A

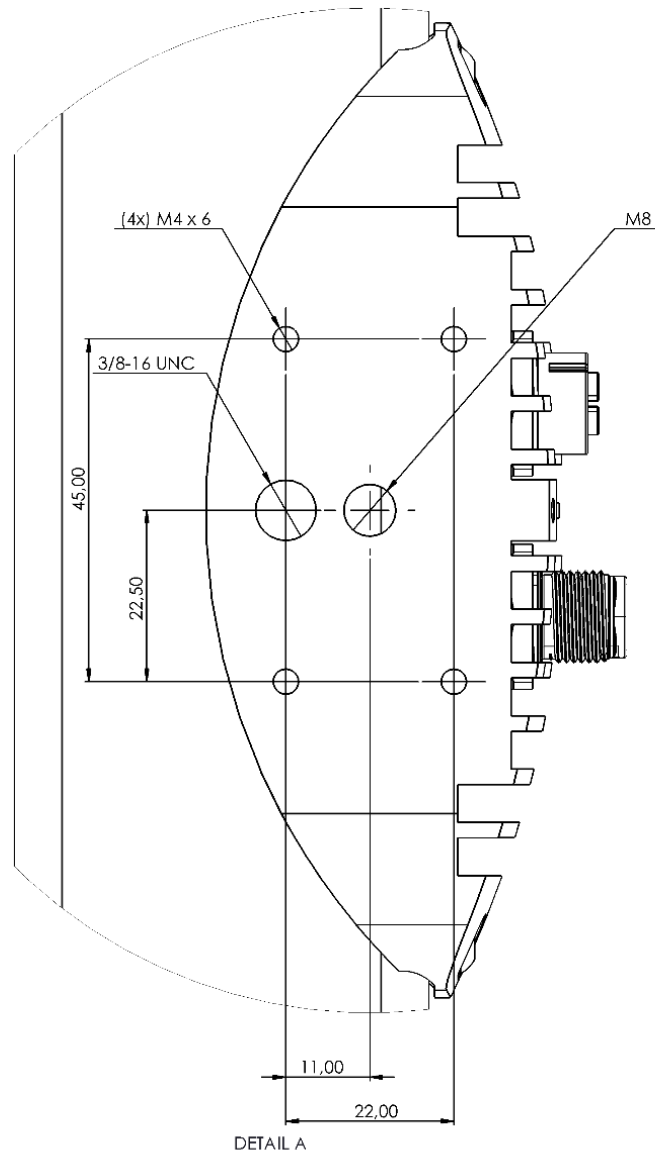


Figure 23: MotionCam-3D Gen 3 - Detail A

Front View: Projection Unit and Camera Unit

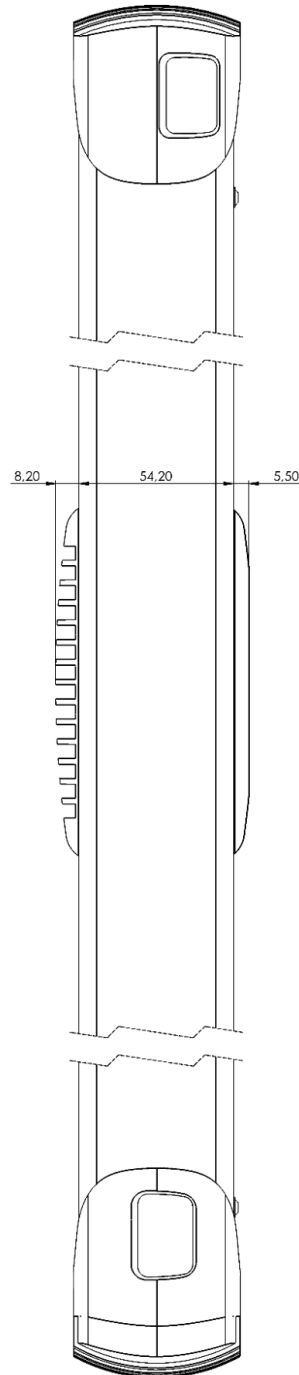


Figure 24: Projection unit and camera of MotionCam-3D Gen 3

MotionCam-3D Version B

Bottom View: Mounting Plate

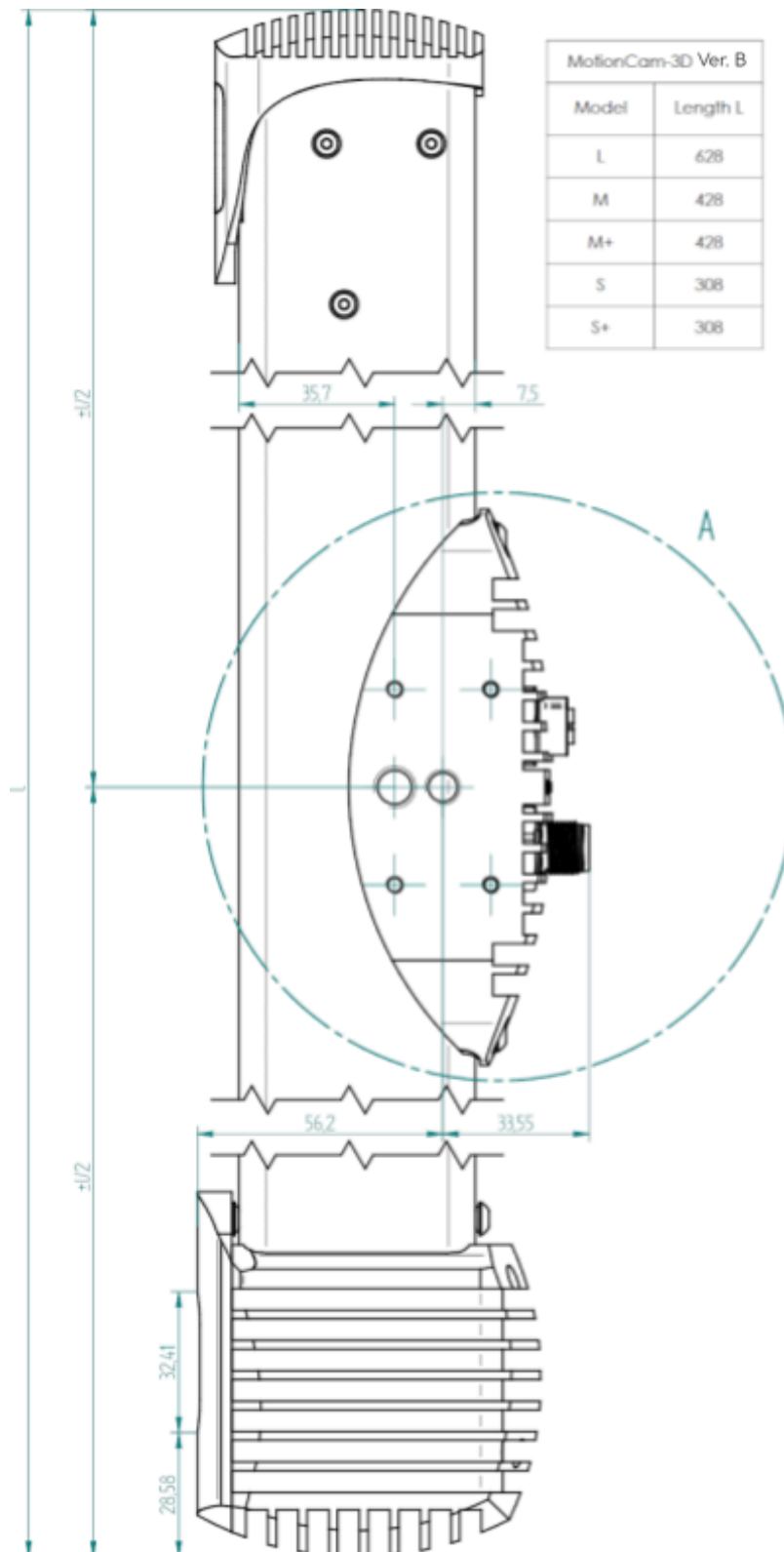
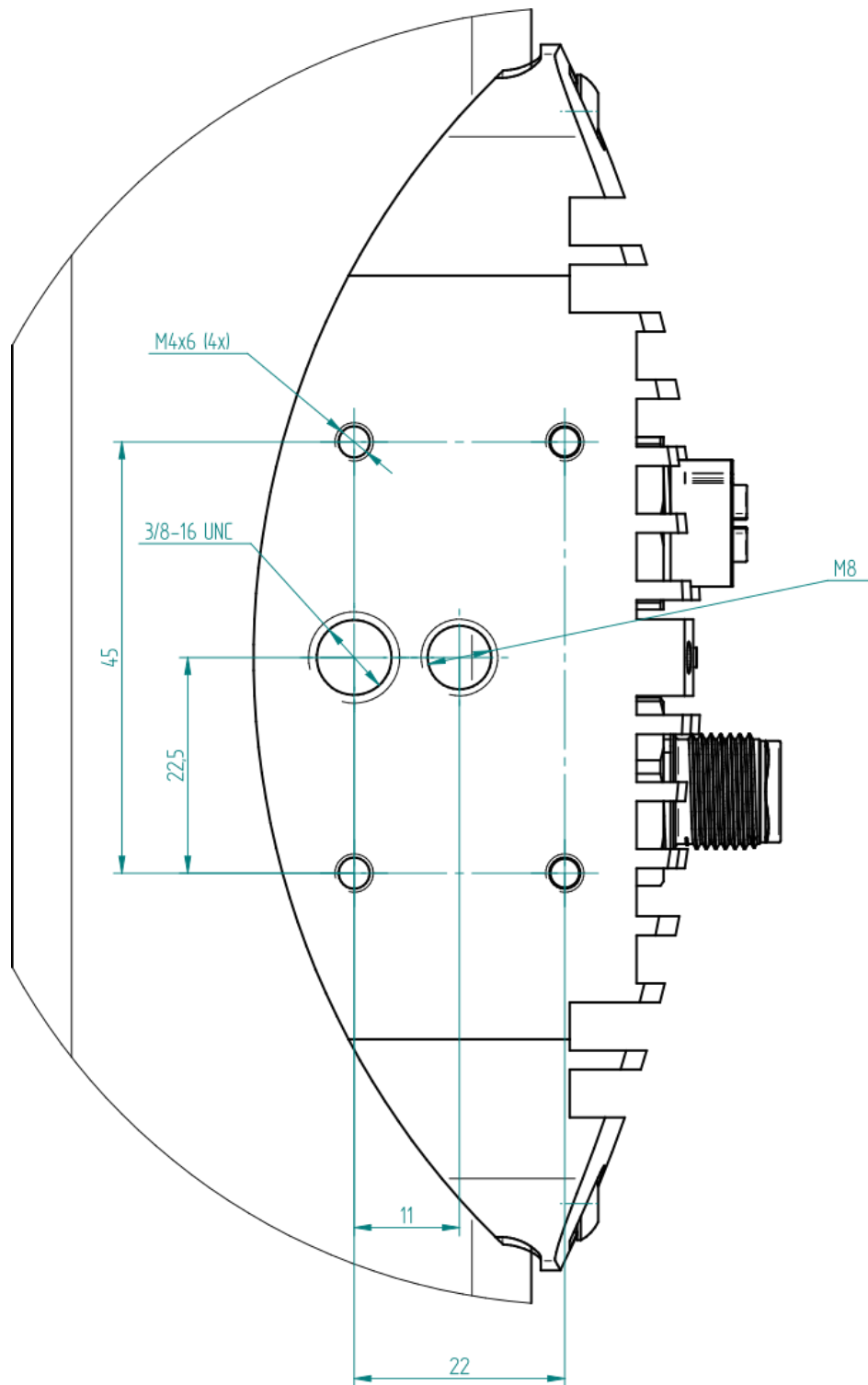


Figure 25: Bottom view of MotionCam-3D Gen 2

Bottom View: Detail A



DETAIL A

Figure 26: MotionCam-3D Gen 2 - Detail A

Front View: Projection Unit and Camera Unit

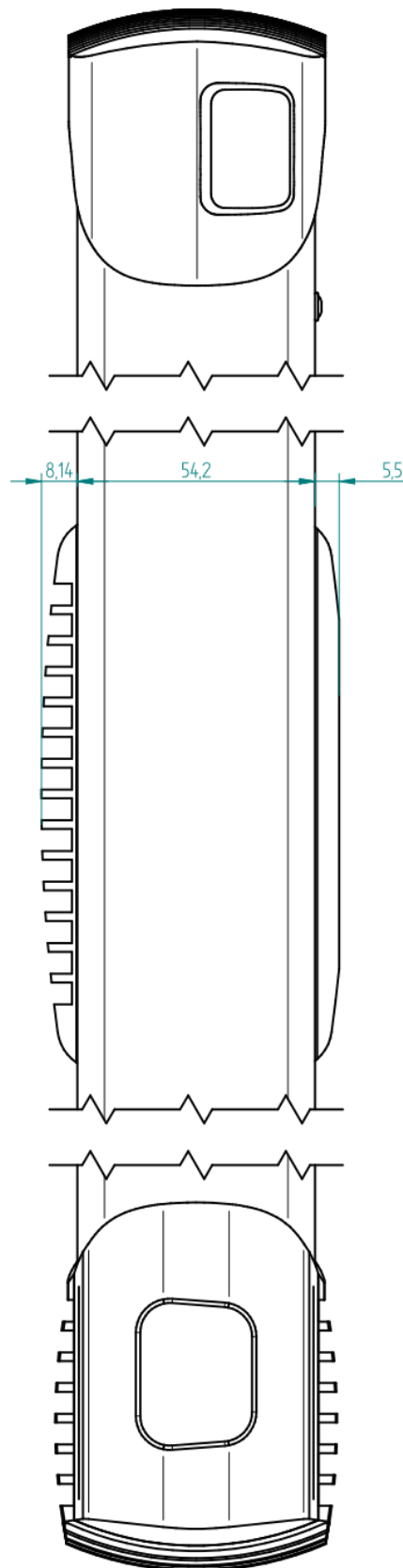
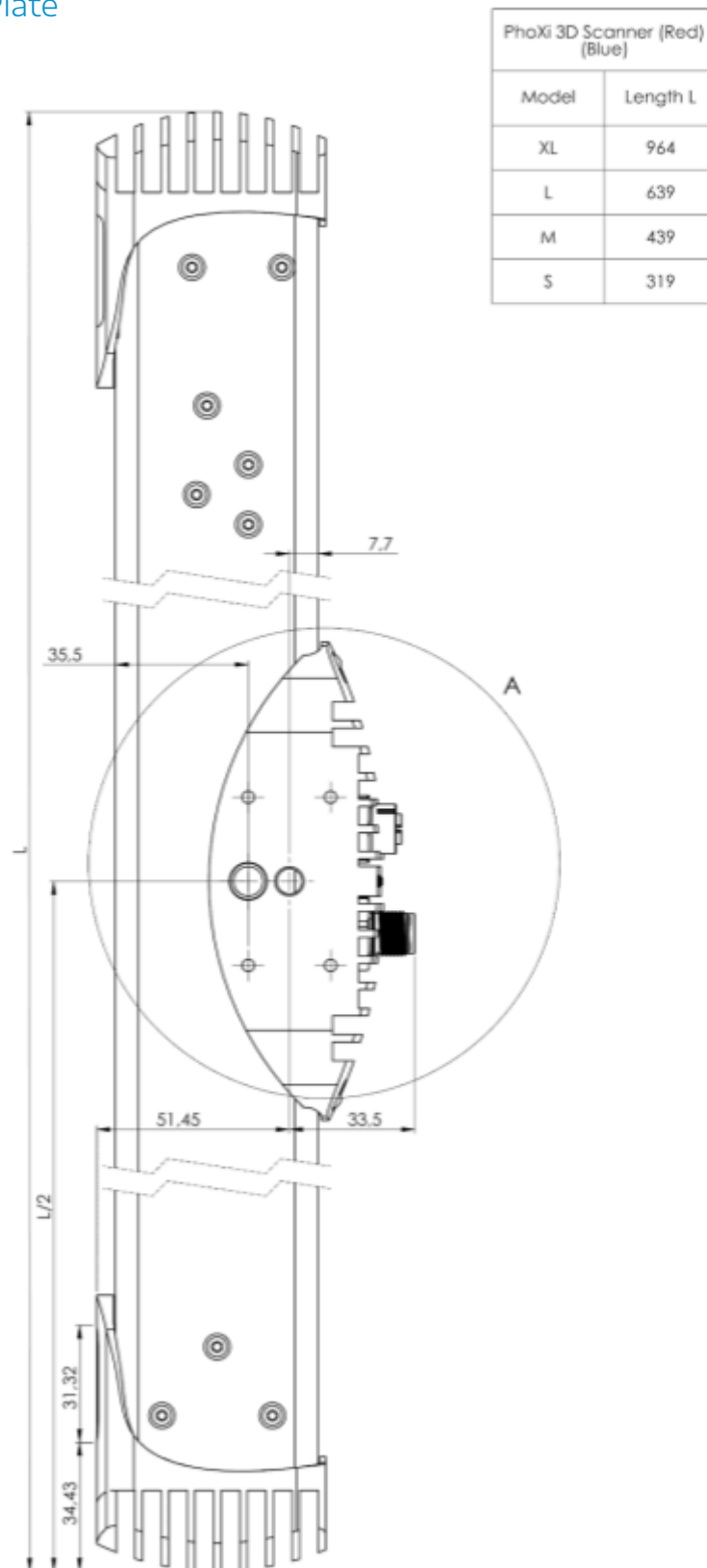


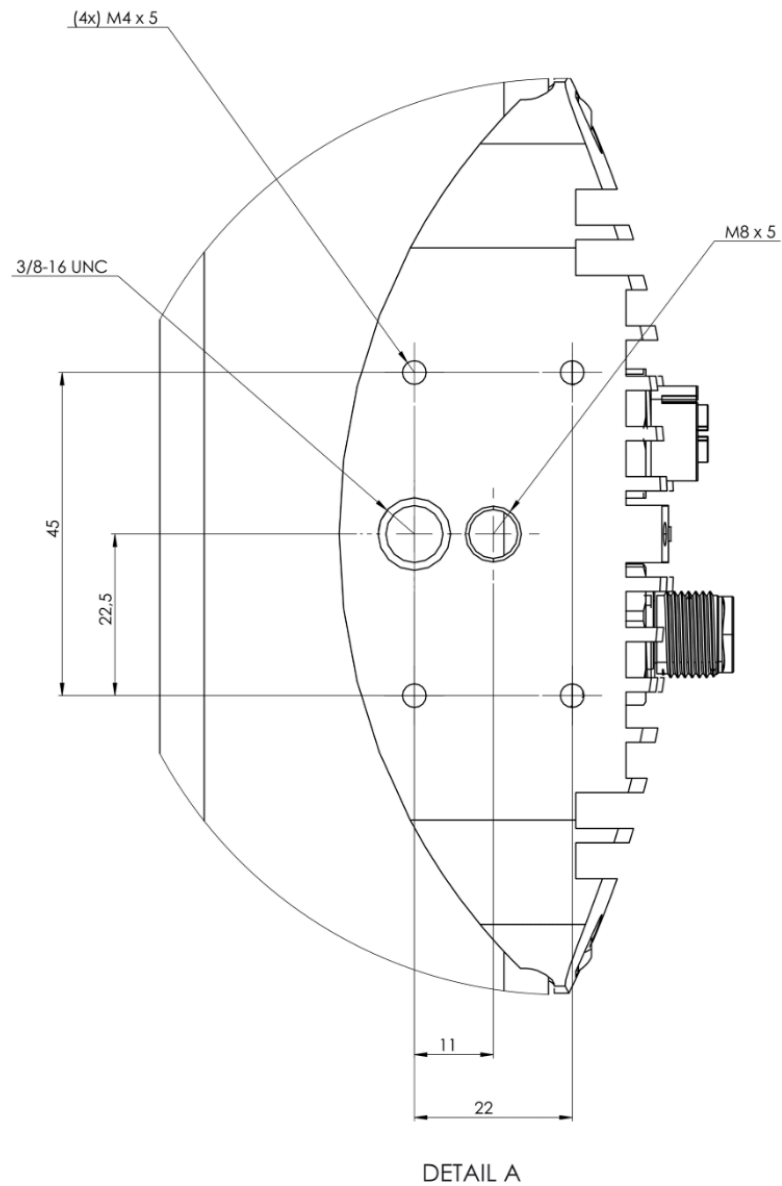
Figure 27: Projection unit and camera of MotionCam-3D Gen 2

PhoXi 3D Scanner Gen 3

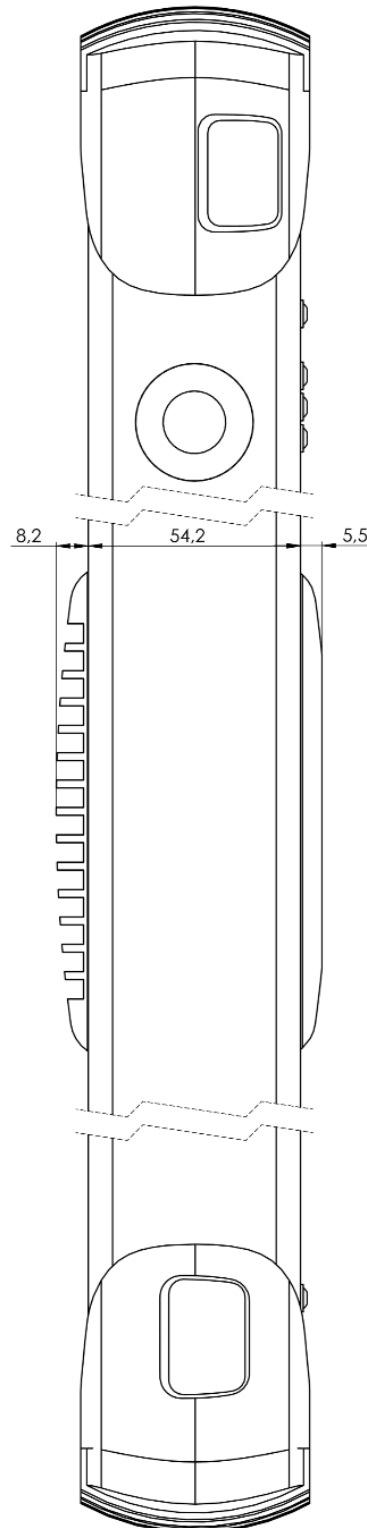
Bottom View: Mounting Plate



Bottom View: Detail A



Front View: Projection Unit and Camera Unit



PhoXi 3D Scanner Gen 2

Bottom View: Mounting Plate

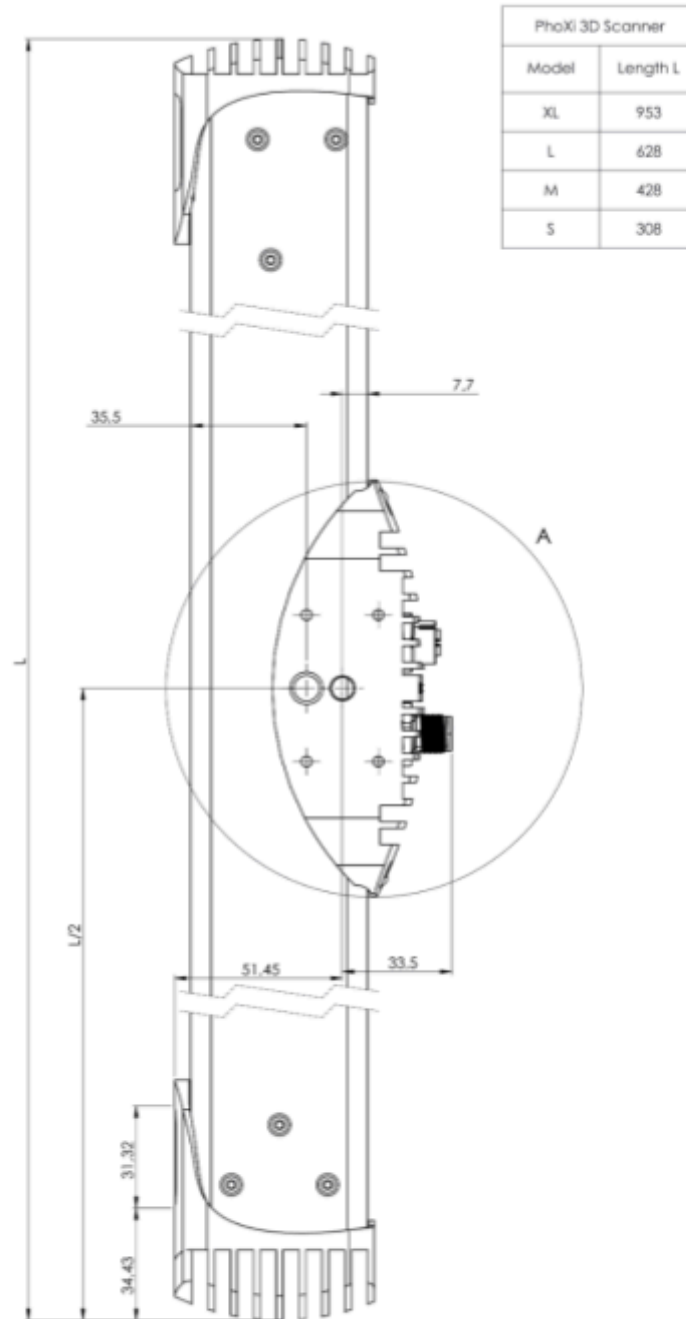


Figure 28: Bottom view of PhoXi 3D Scanner

Bottom View: Detail A

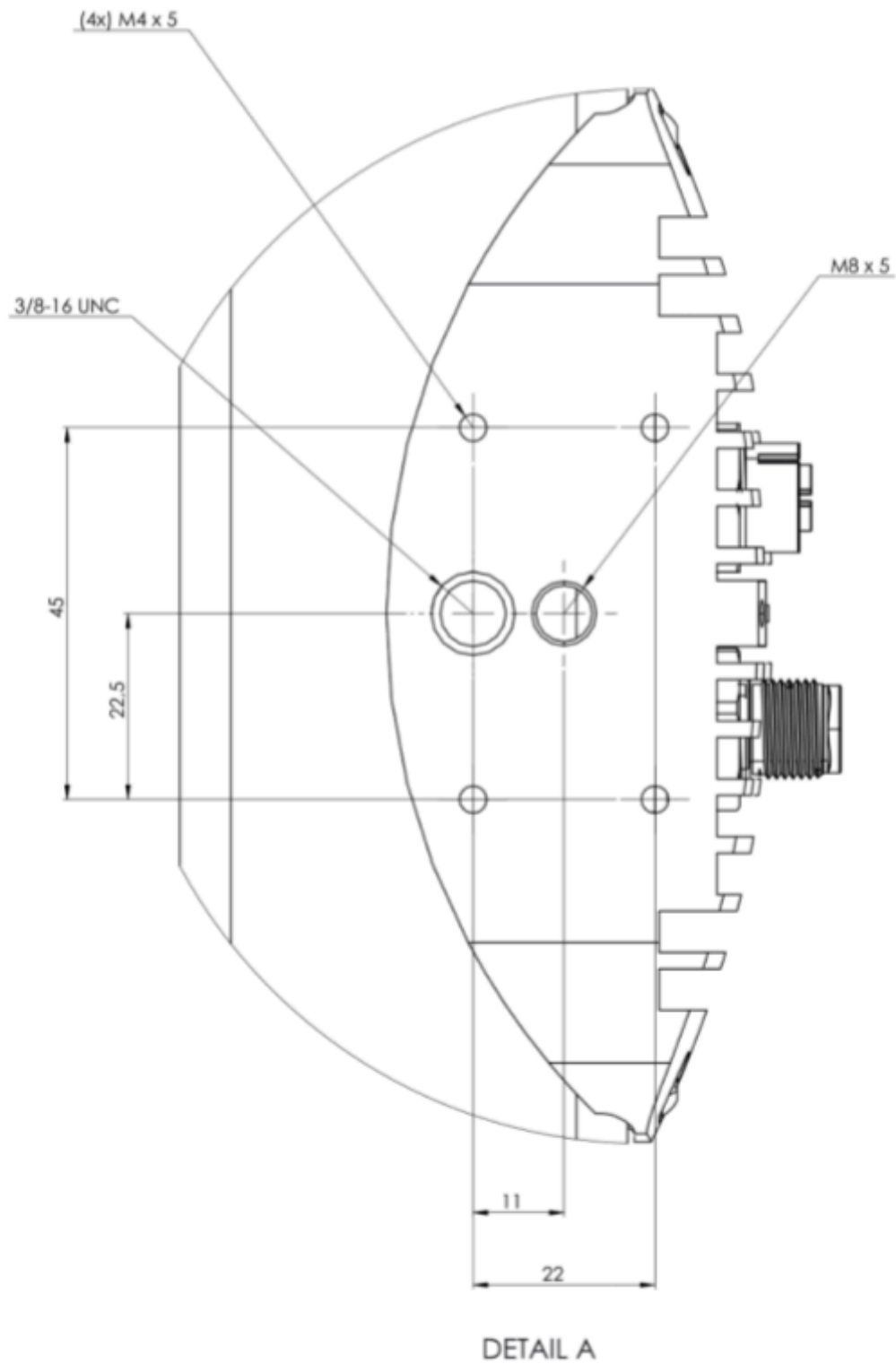


Figure 29: PhoXi 3D Scanner - Detail A

Front View: Projection Unit and Camera Unit

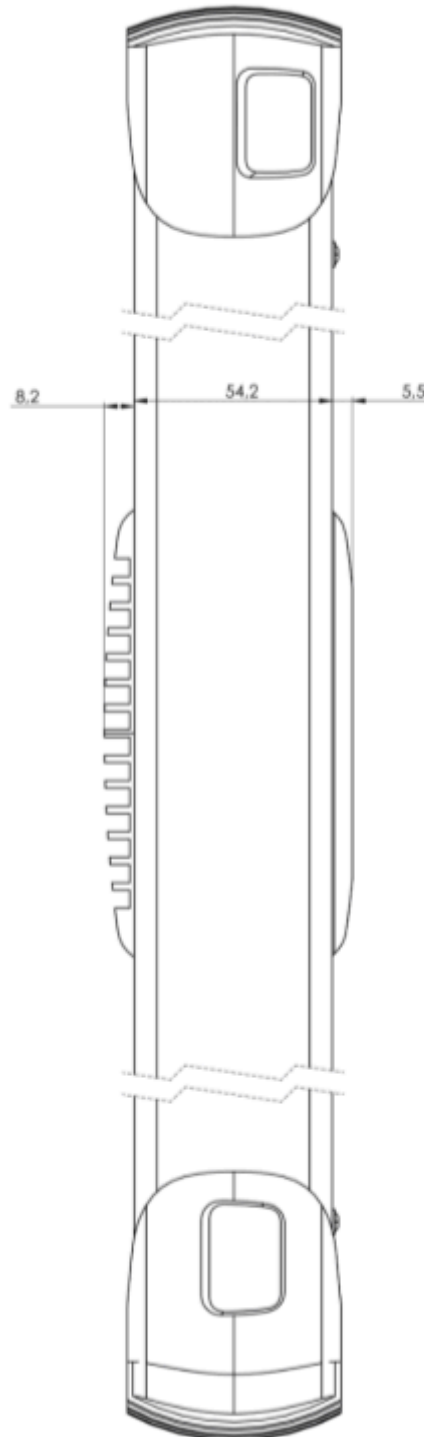


Figure 30: Projection unit and camera of PhoXi 3D Scanner

Alpha 3D Scanner

Bottom View: Mounting Plate

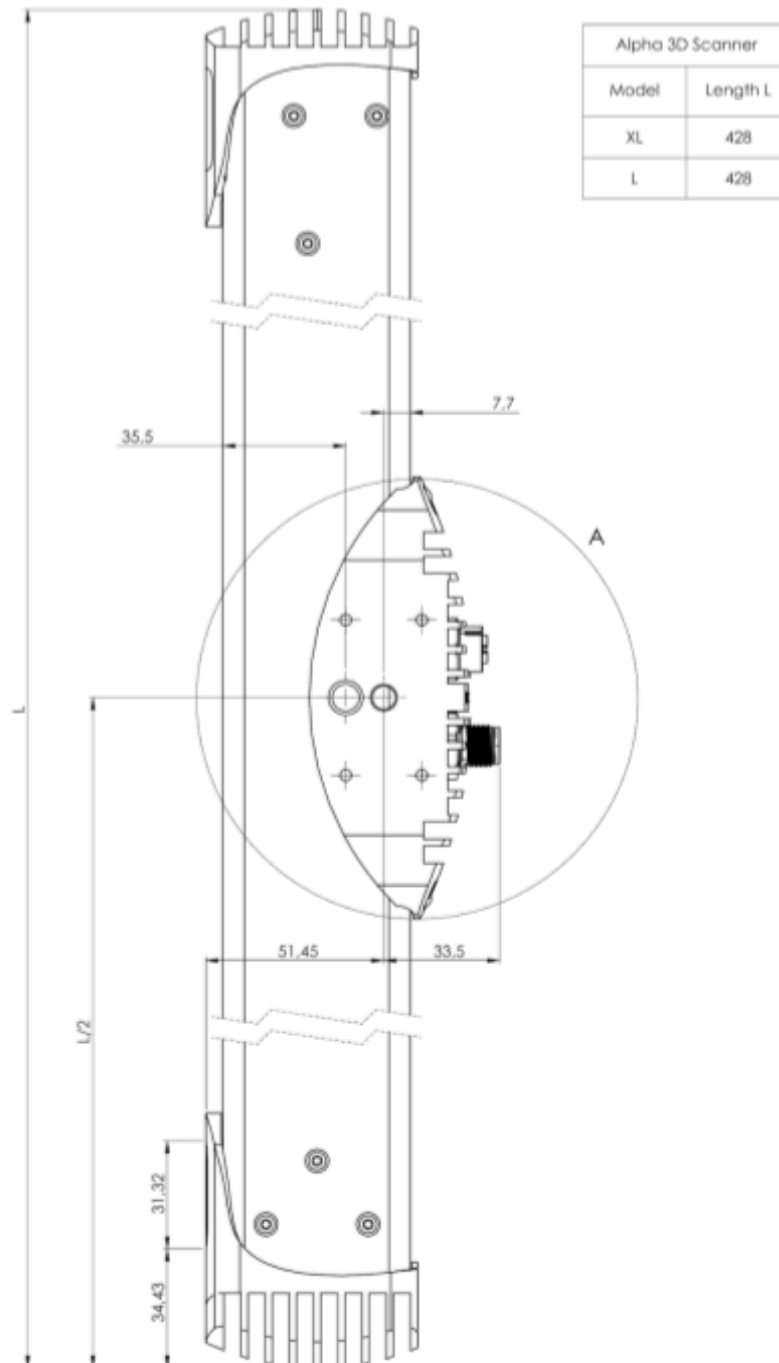


Figure 31: Bottom view of Alpha 3D Scanner

Bottom View: Detail A

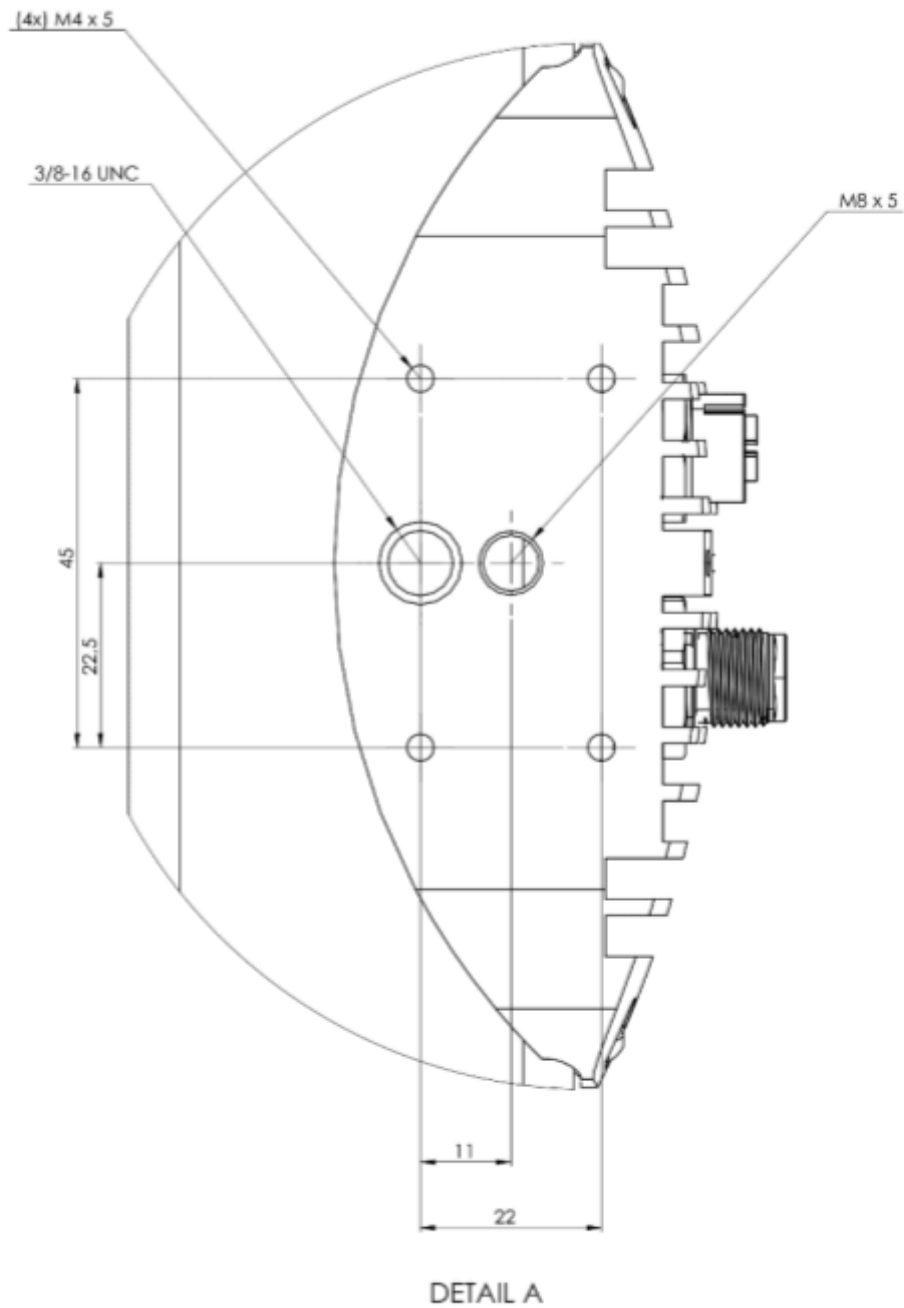


Figure 32: Alpha 3D Scanner - Detail A

Front View: Projection Unit and Camera Unit

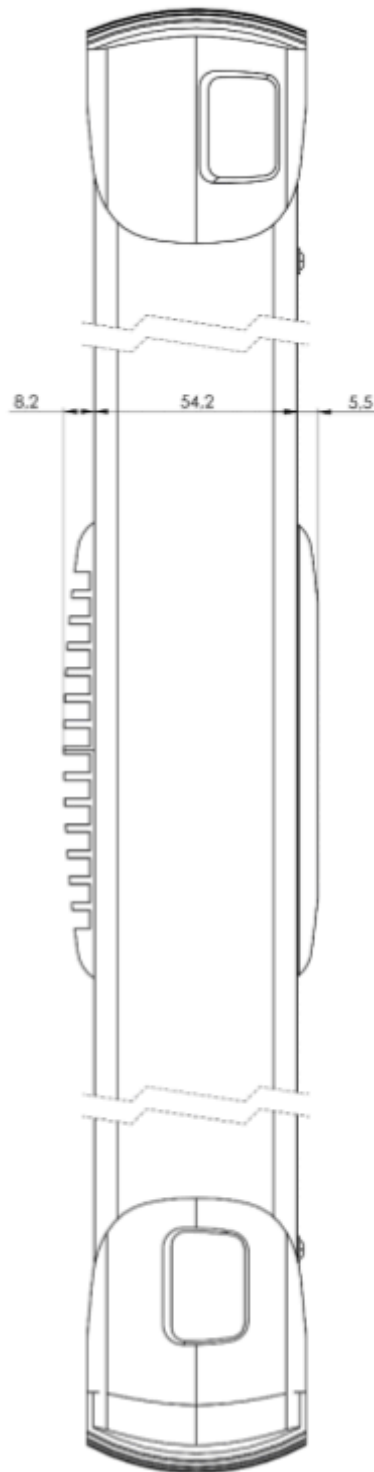


Figure 33: Projection unit and camera of Alpha 3D Scanner

Warranty

A standard 1-year warranty applies. Full warranty conditions are stated in the General Terms and Conditions on the Photoneo website: <https://www.photoneo.com/kb/tc>

Contact Information

Headquarters:

Zebra Technologies Slovakia s.r.o.
Plynárenská 6
821 09 Bratislava,
Slovakia

Technical support

Contact us at the [Help Center](#).

Visit Photoneo support pages at www.photoneo.com/support.

Orders and inquiries:
photoneo-sales@zebra.com
photoneo-sales-us@zebra.com

